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(54) **VERTICAL CHANNEL TRANSISTOR WITH SELF-ALIGNED GATE ELECTRODE AND METHOD FOR FABRICATING THE SAME**

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(73) Assignee: **SK hynix Inc.**

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H01L 29/66 (2006.01)

H01L 29/423 (2006.01)

(52) **U.S. Cl.**

CPC ***H01L 29/66666*** (2013.01); ***H01L 29/42356*** (2013.01)

USPC **438/268**

(57) **ABSTRACT**

A method for fabricating vertical channel transistors includes forming a plurality of pillars which have laterally opposing both sidewalls, over a substrate; forming a gate dielectric layer on both sidewalls of the pillars; forming first gate electrodes which cover any one sidewalls of the pillars and shield gate electrodes which cover the other sidewalls of the pillars and have a height lower than the first gate electrodes, over the gate dielectric layer; and forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes.

FIG. 1A

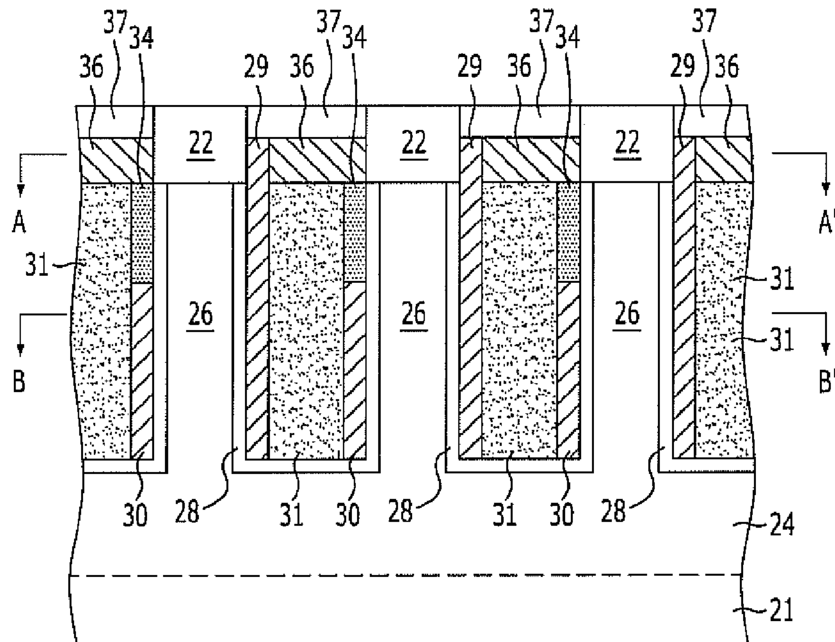


FIG. 1B

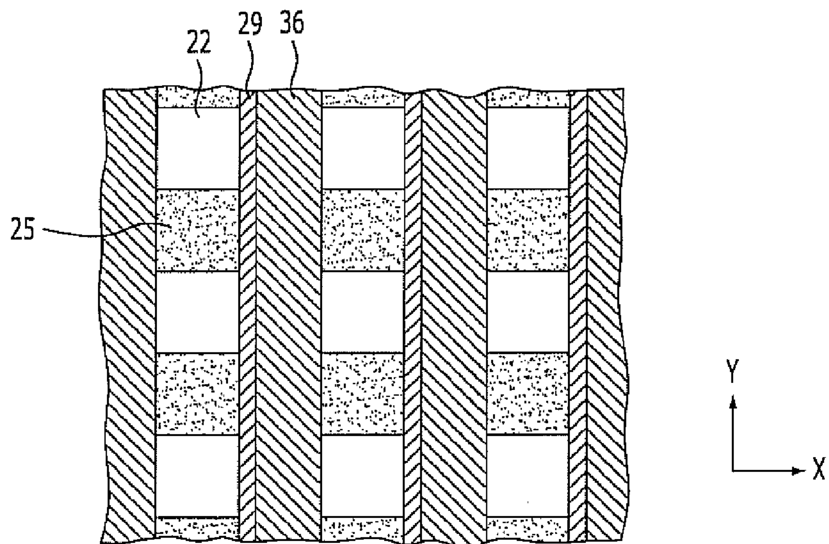


FIG. 1C

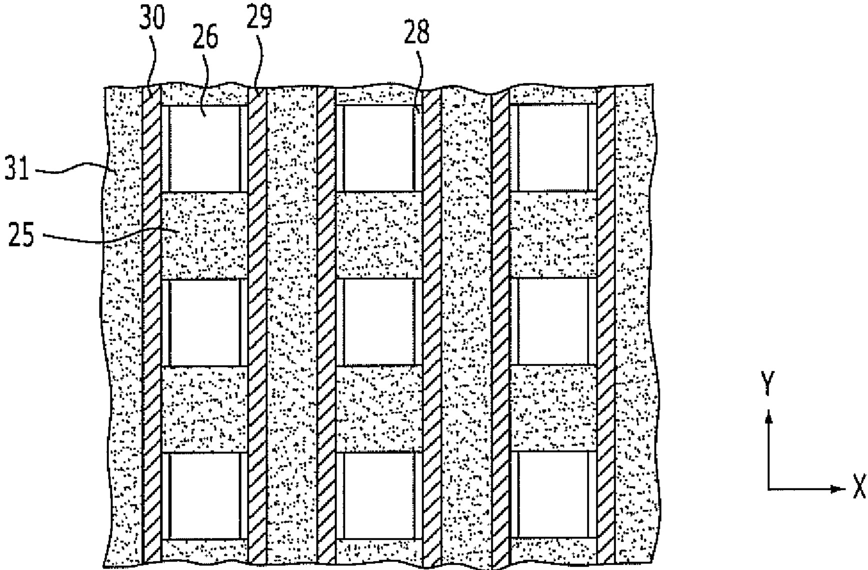


FIG. 2

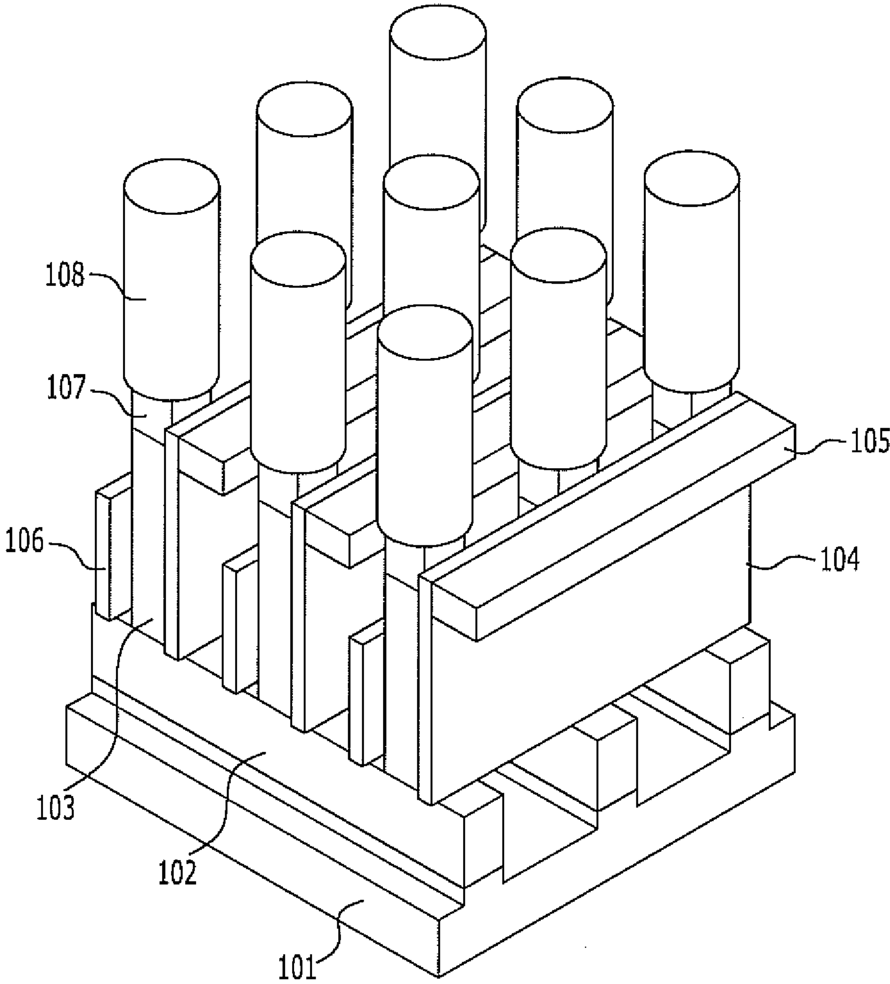


FIG. 3A

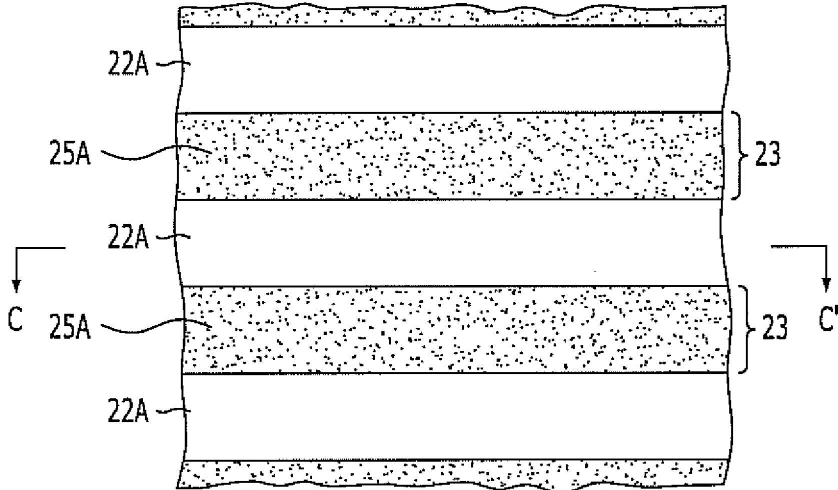


FIG. 3B

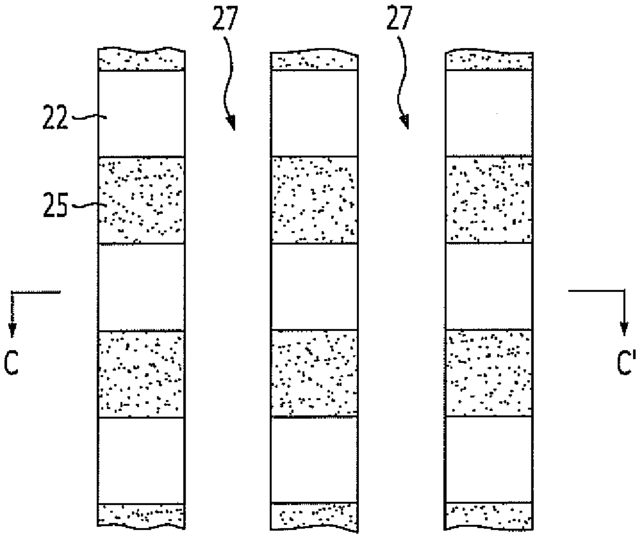


FIG. 3C

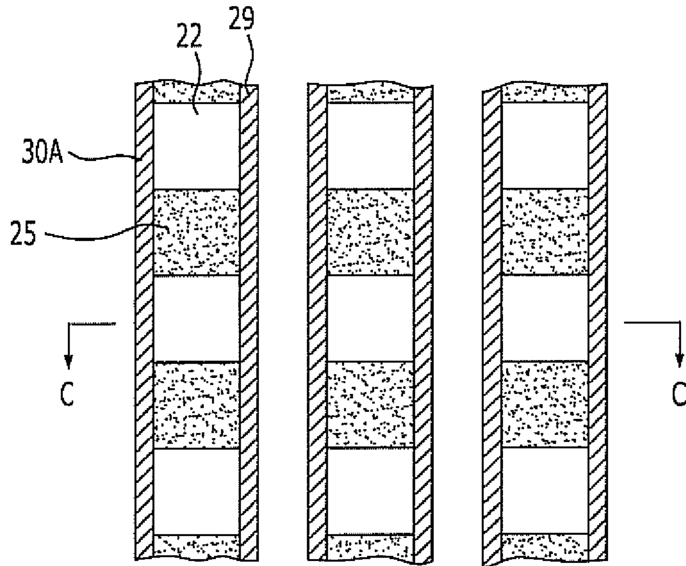


FIG. 3D

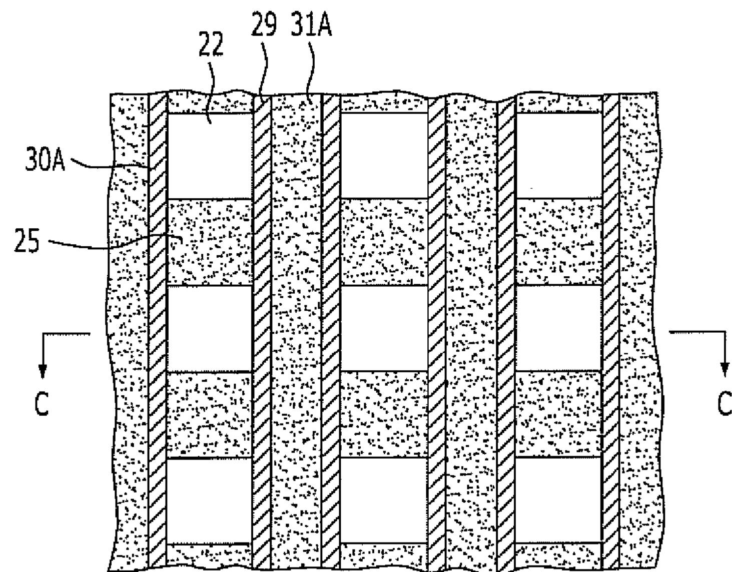


FIG. 3E

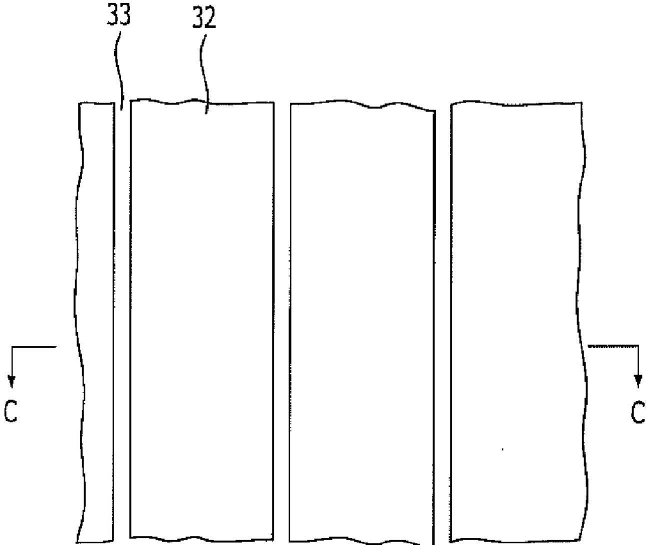


FIG. 3F

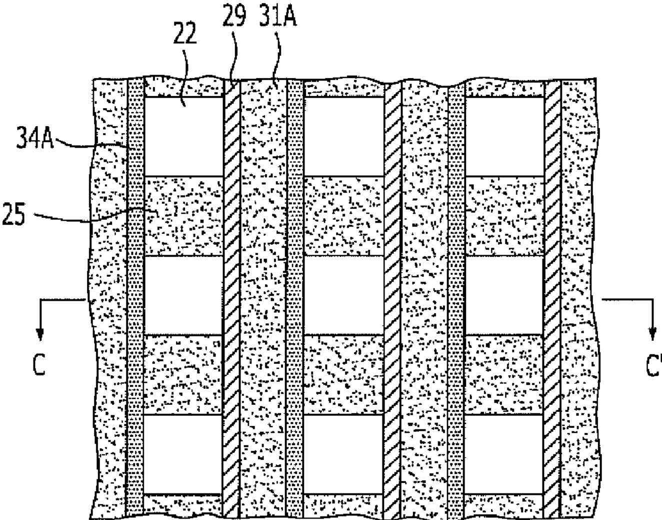


FIG. 3G

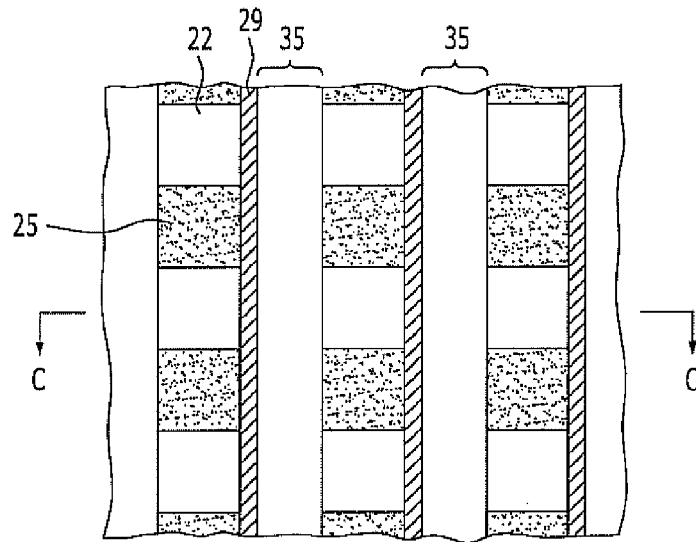


FIG. 3H

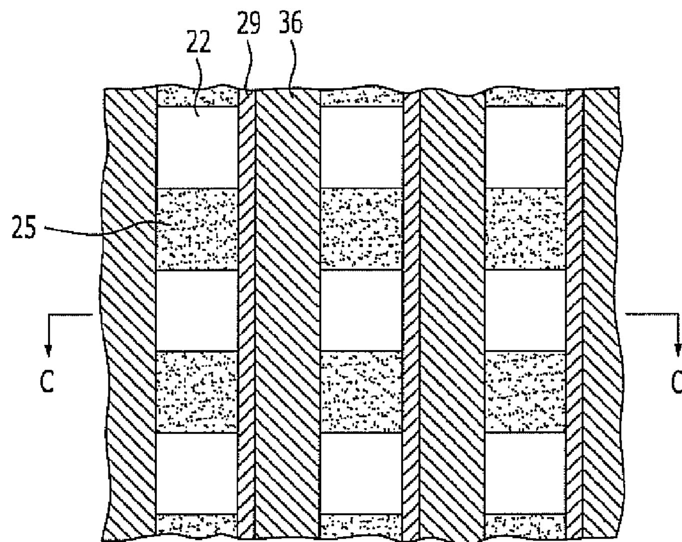


FIG. 3I

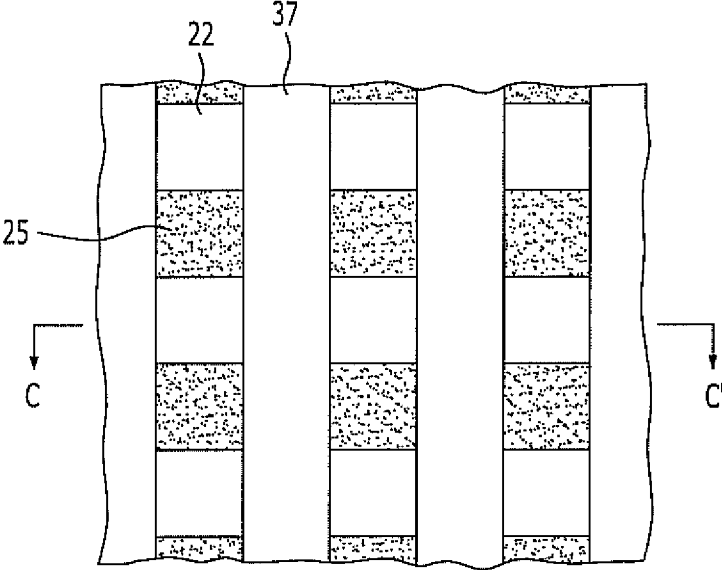


FIG. 4A

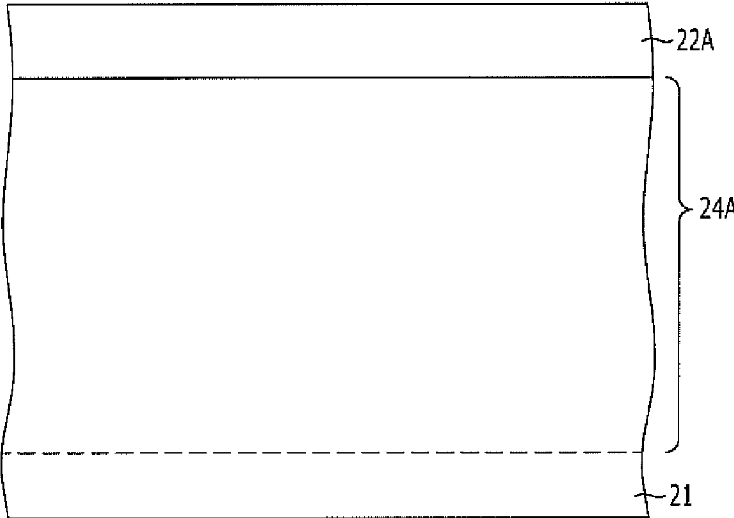


FIG. 4B

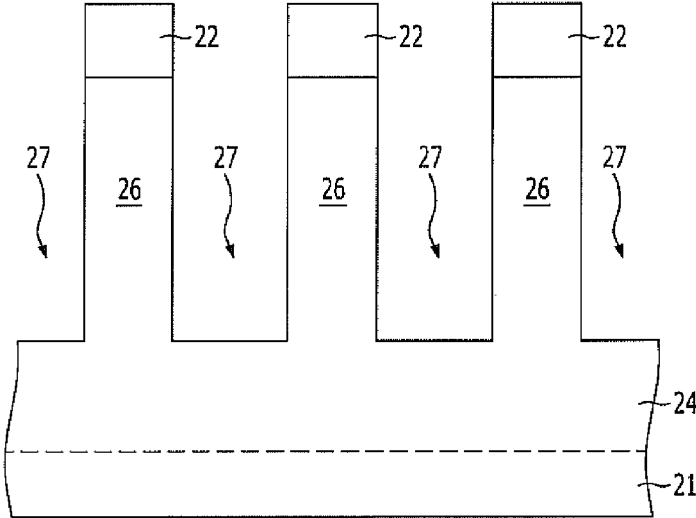


FIG. 4C

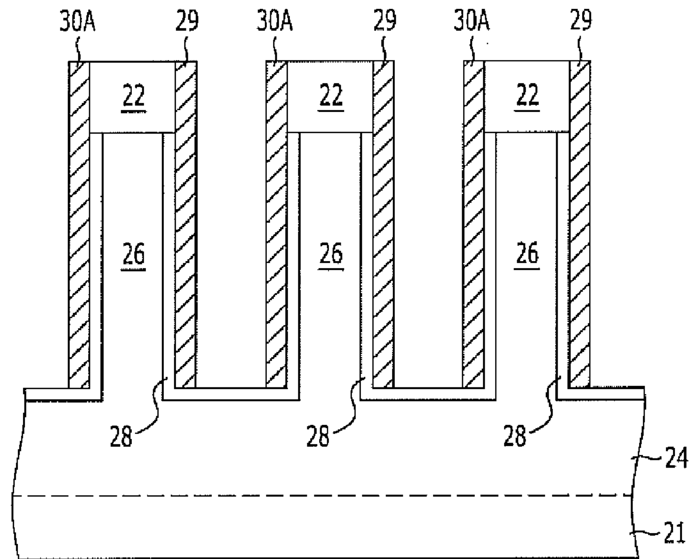


FIG. 4D

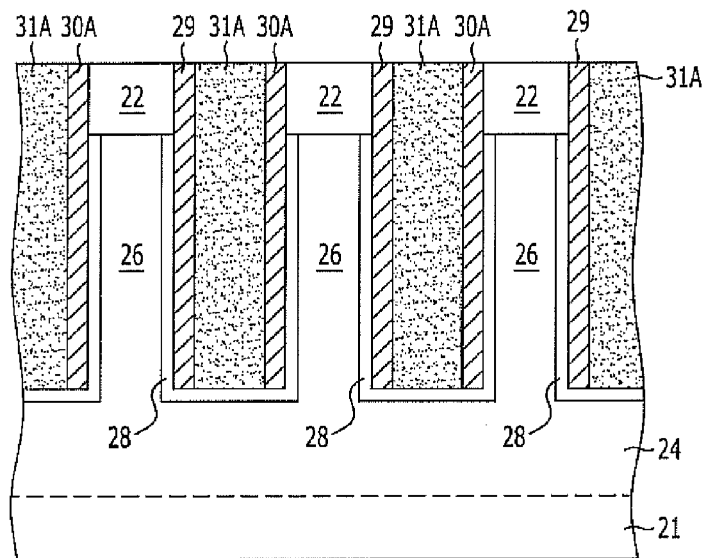


FIG. 4E

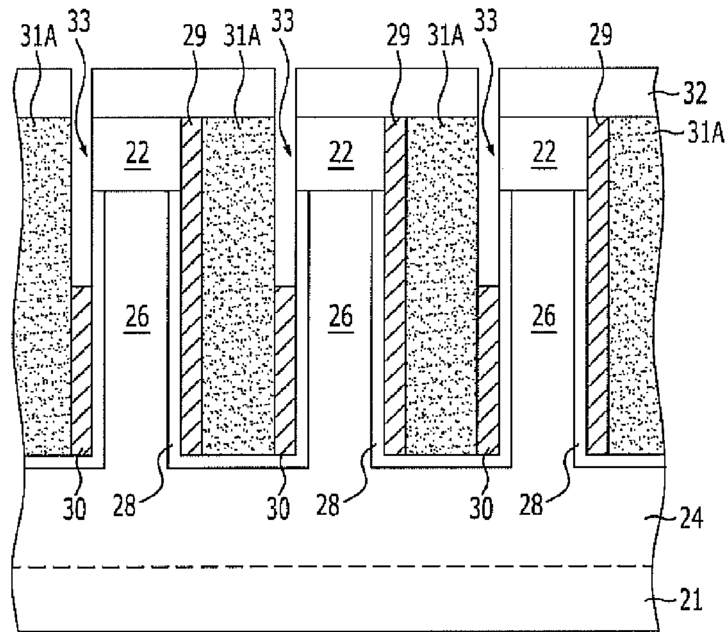


FIG. 4F

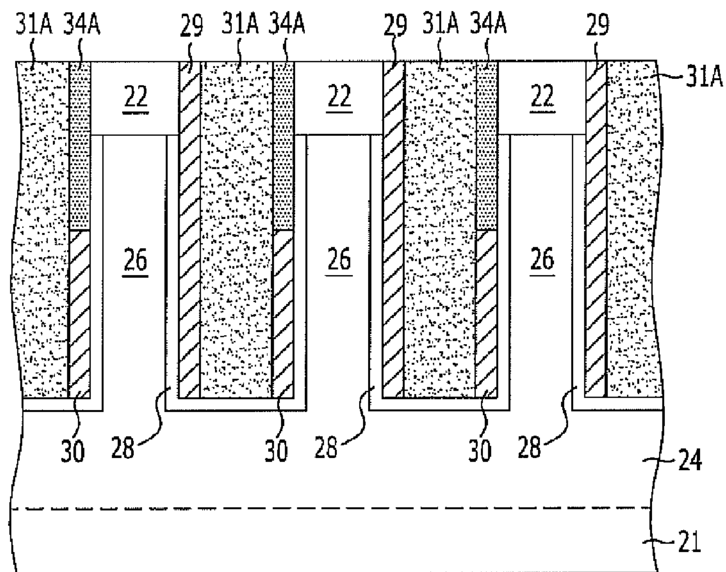


FIG. 4G

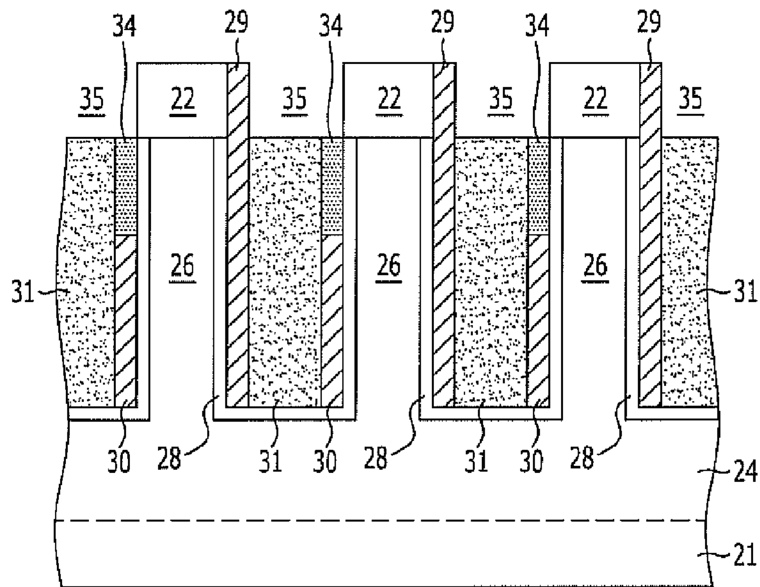


FIG. 4H

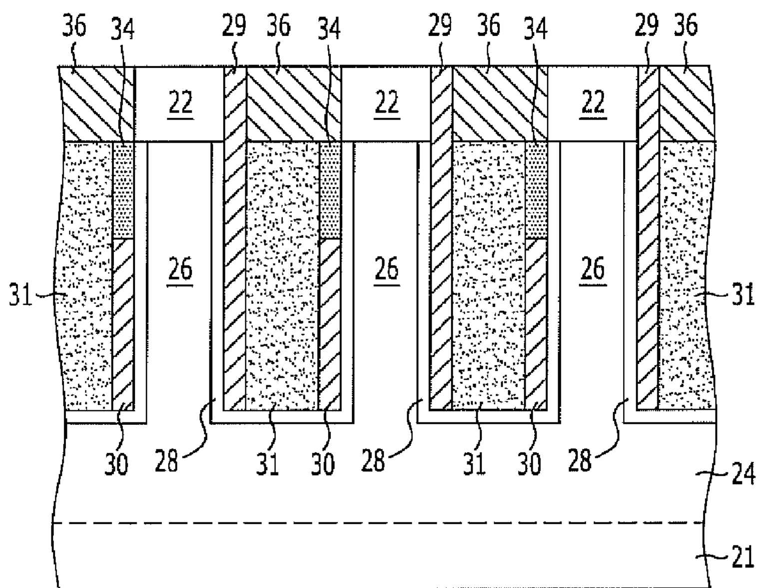


FIG. 4I

FIG. 5A

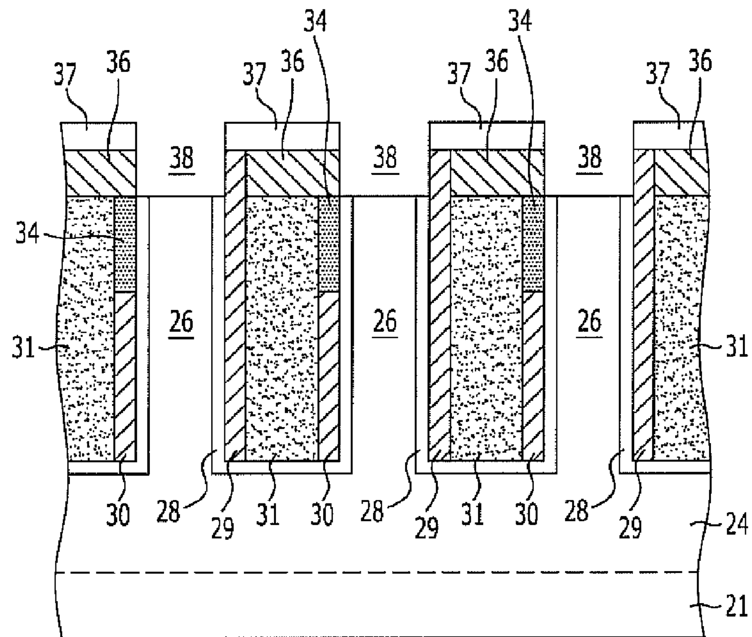


FIG. 5B

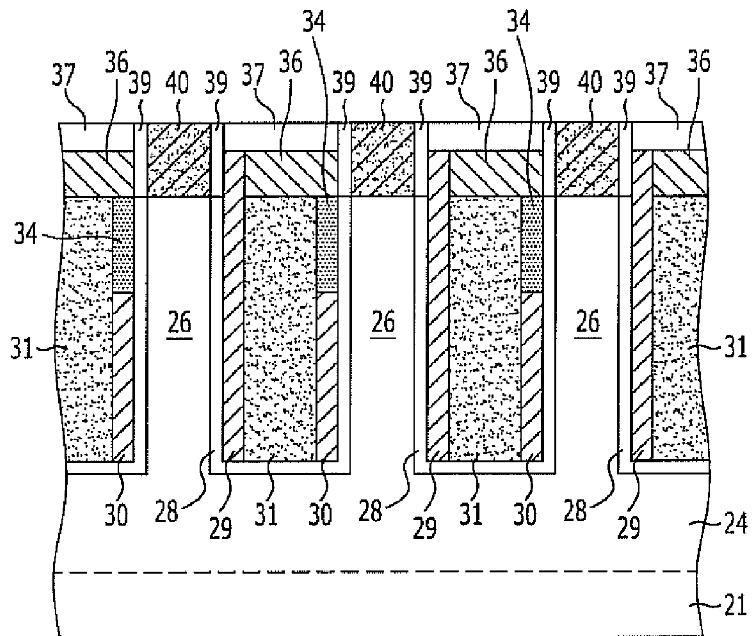


FIG. 5C

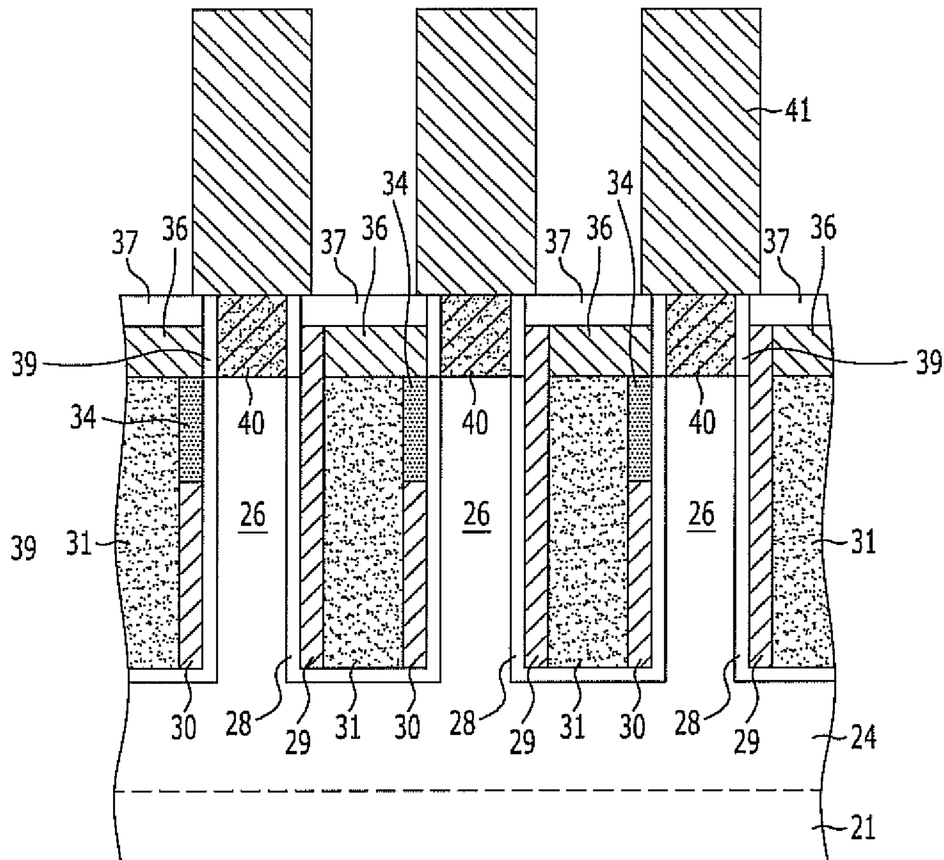


FIG. 6

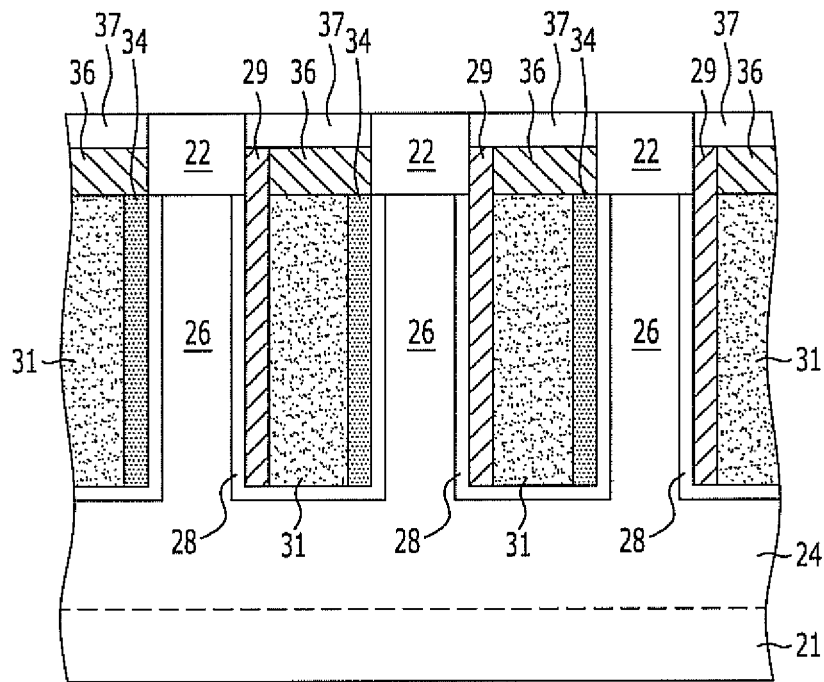


FIG. 7

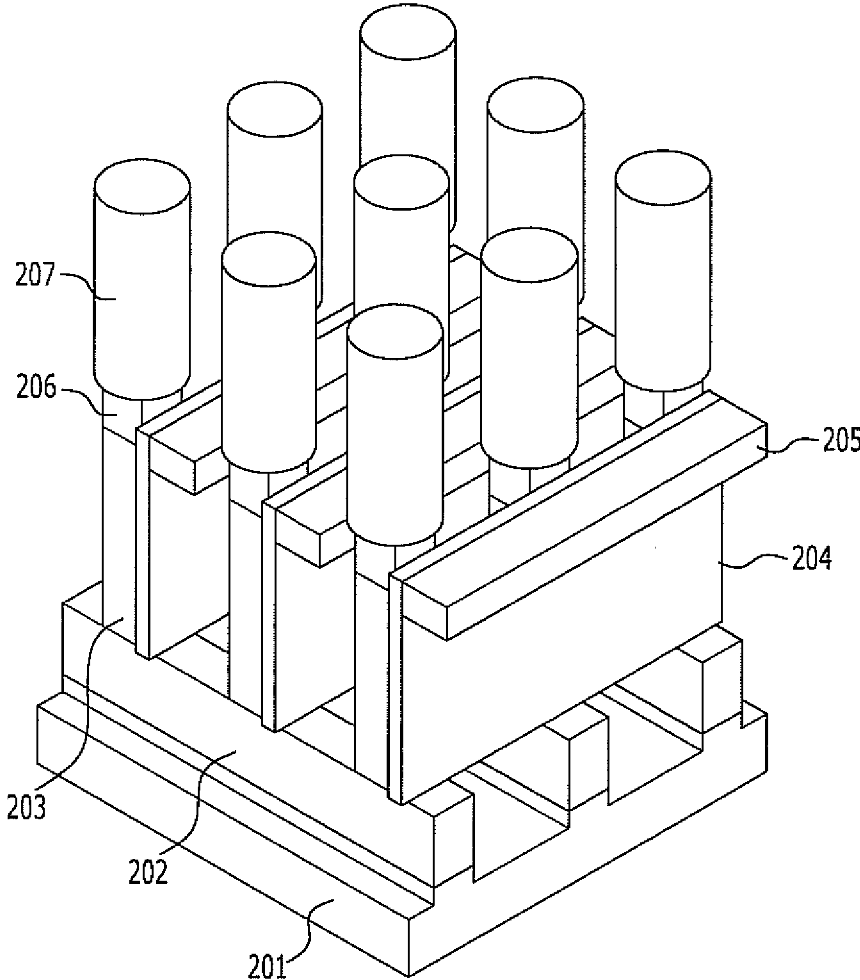


FIG. 8A

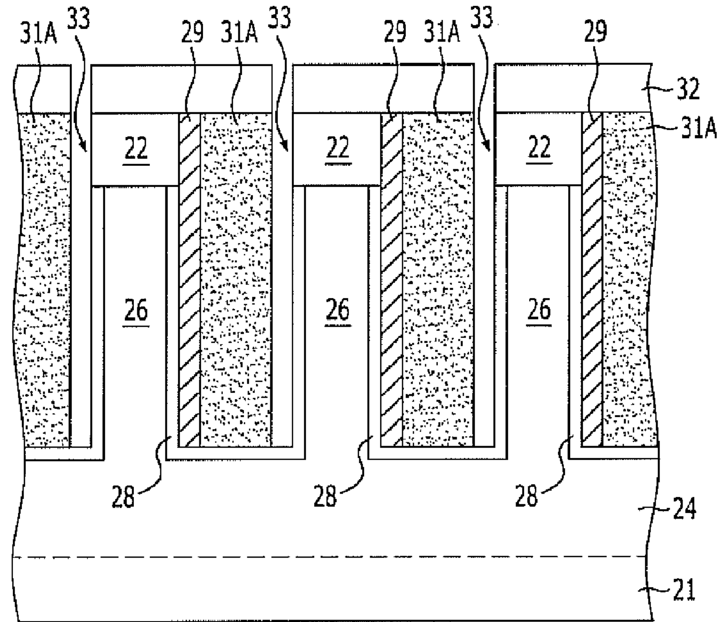


FIG. 8B

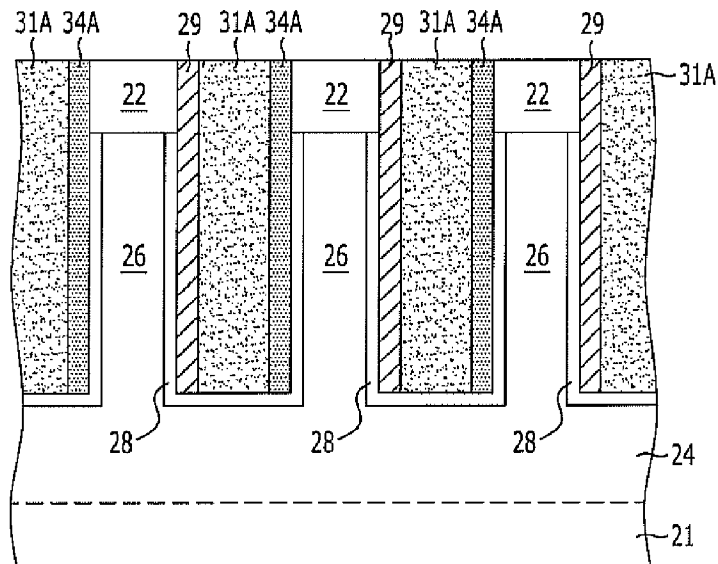


FIG. 8C

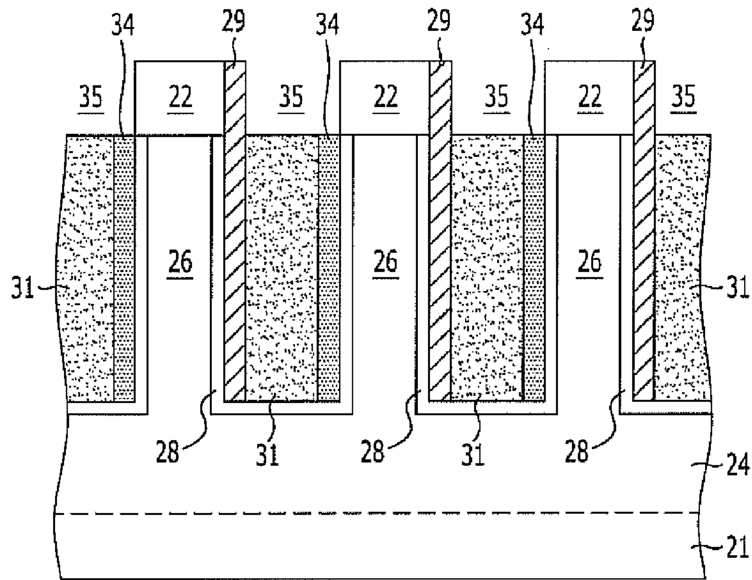


FIG. 8D

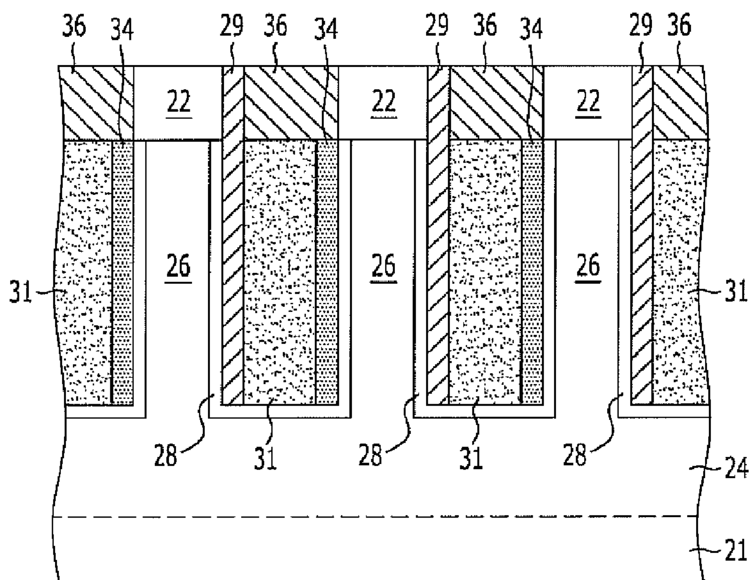


FIG. 8E

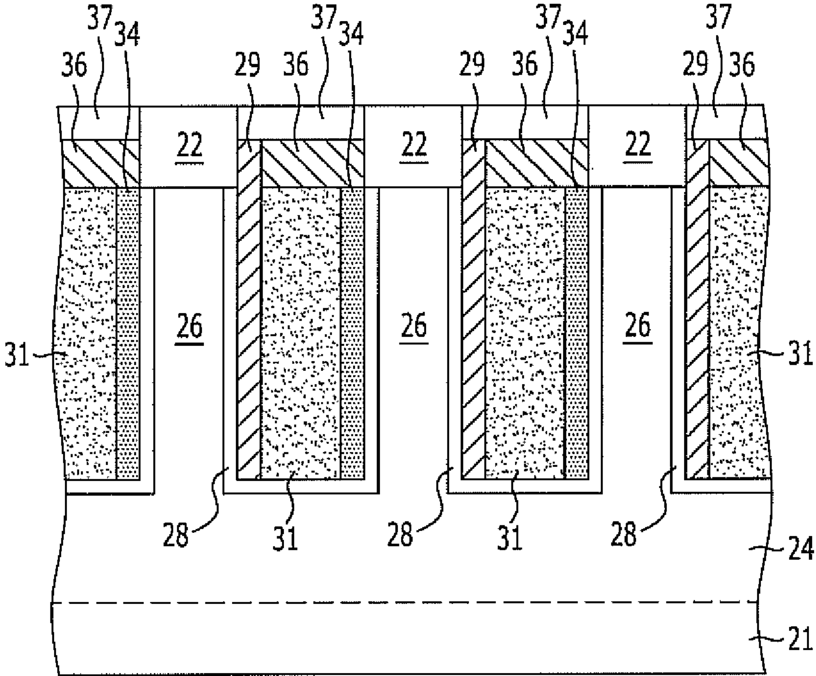


FIG. 9

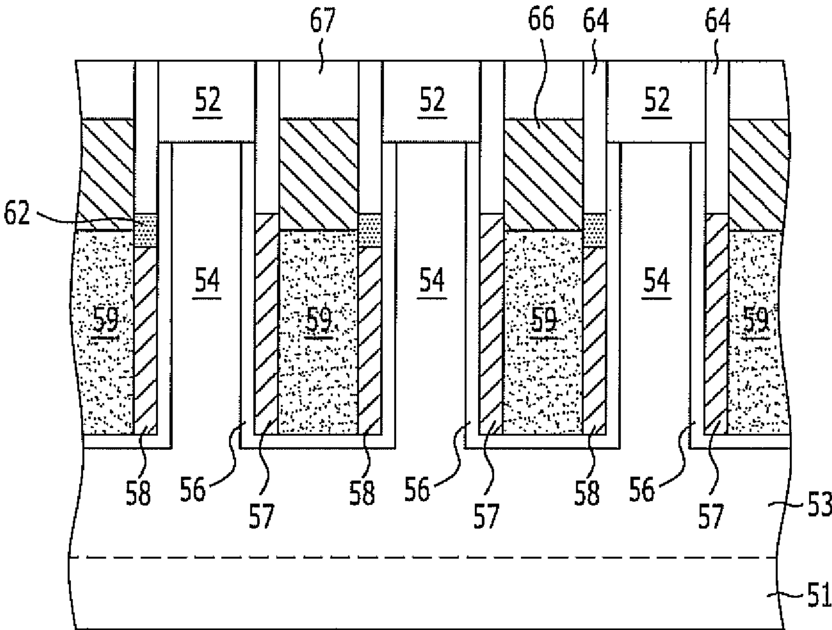


FIG. 10

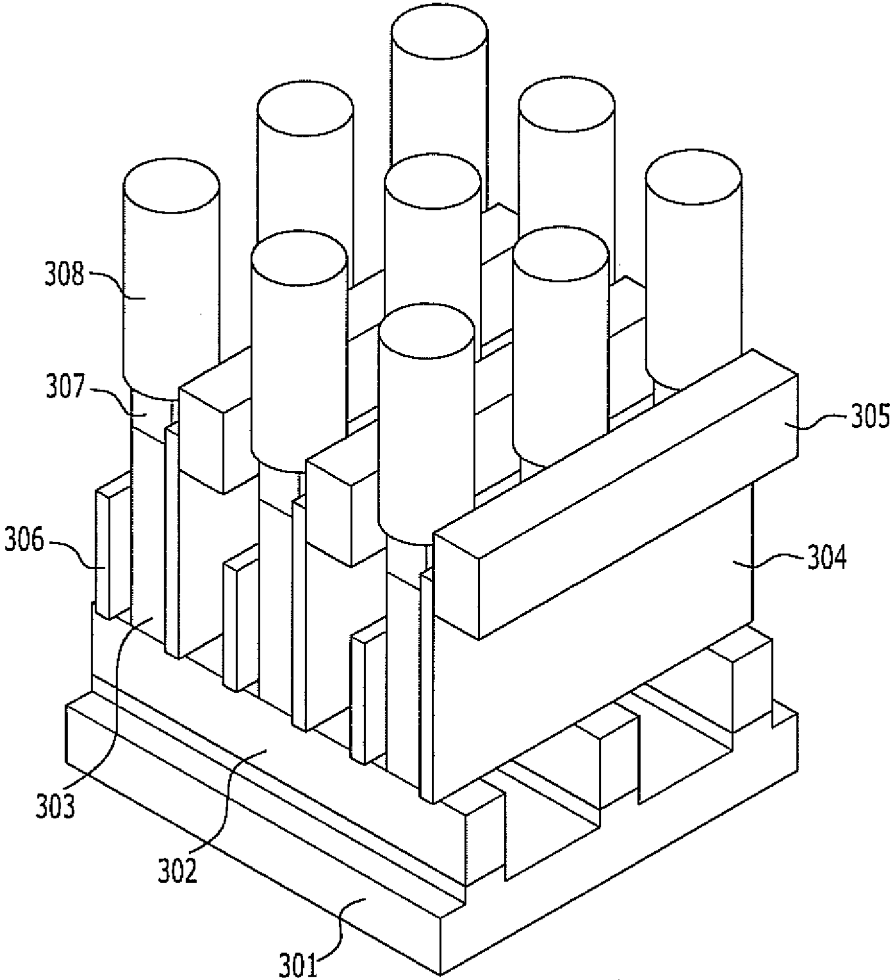


FIG. 11A

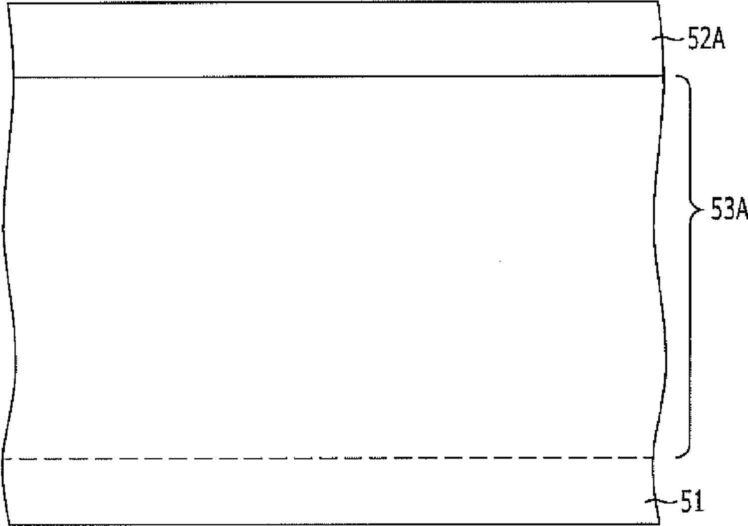


FIG. 11B

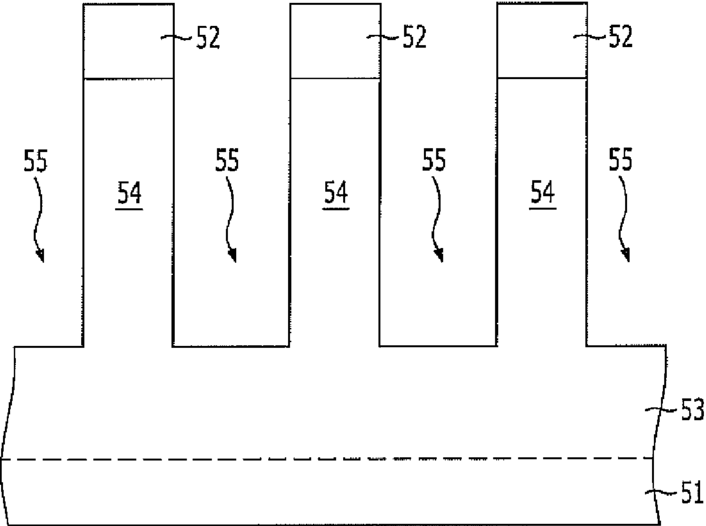


FIG. 11C

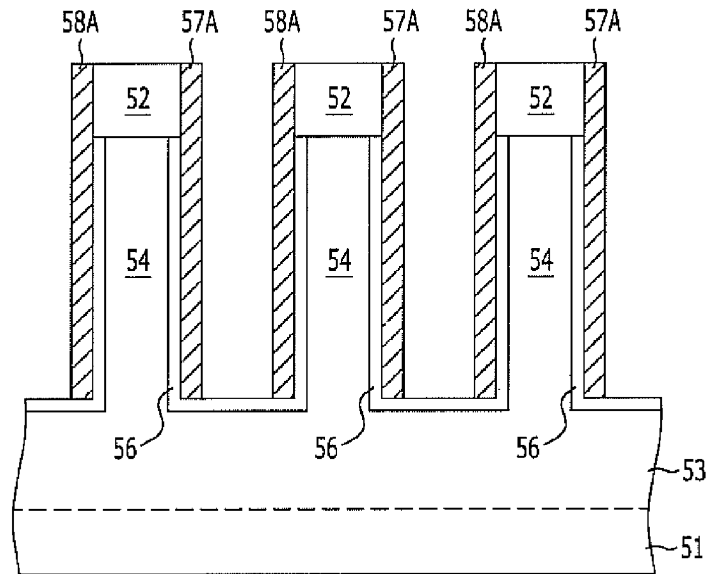


FIG. 11D

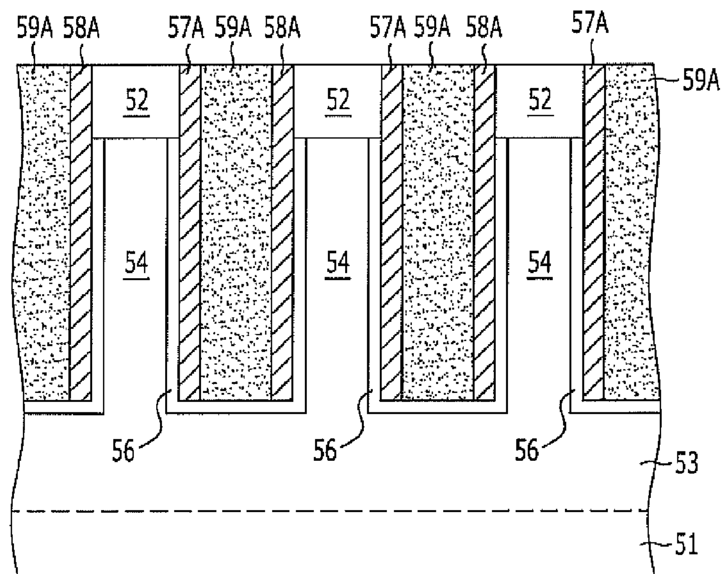


FIG. 11E

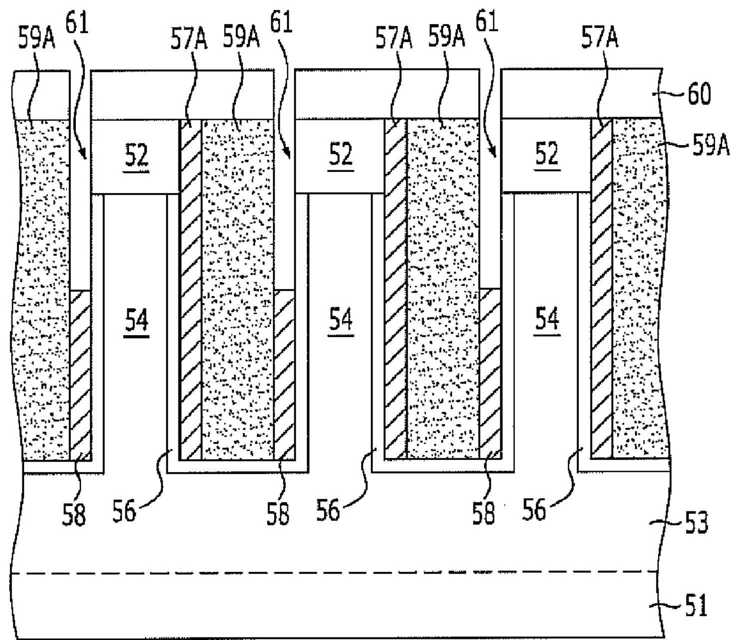


FIG. 11F

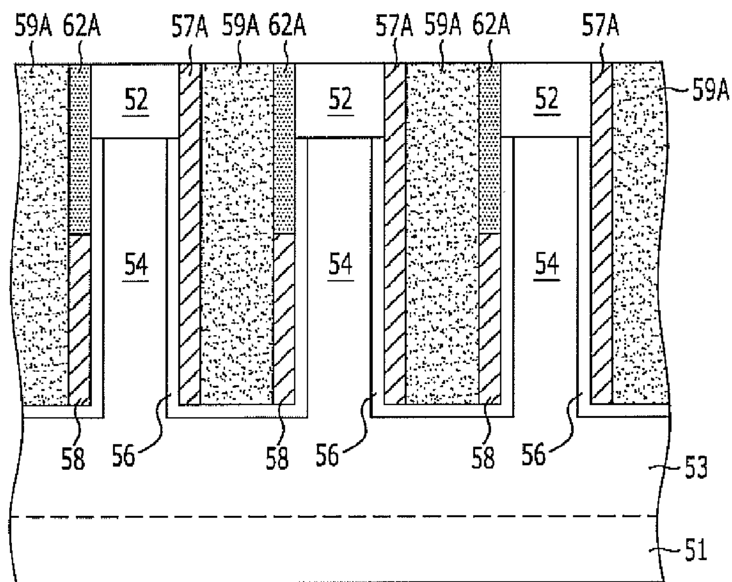


FIG. 11G

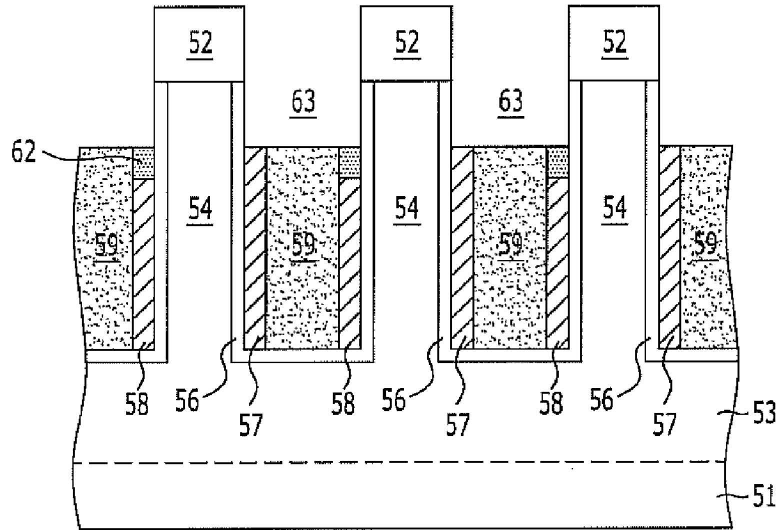


FIG. 11H

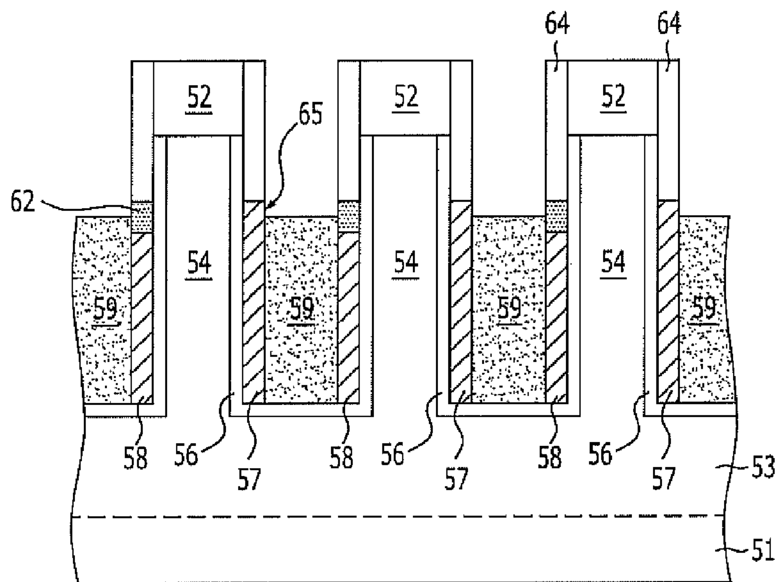


FIG. 11I

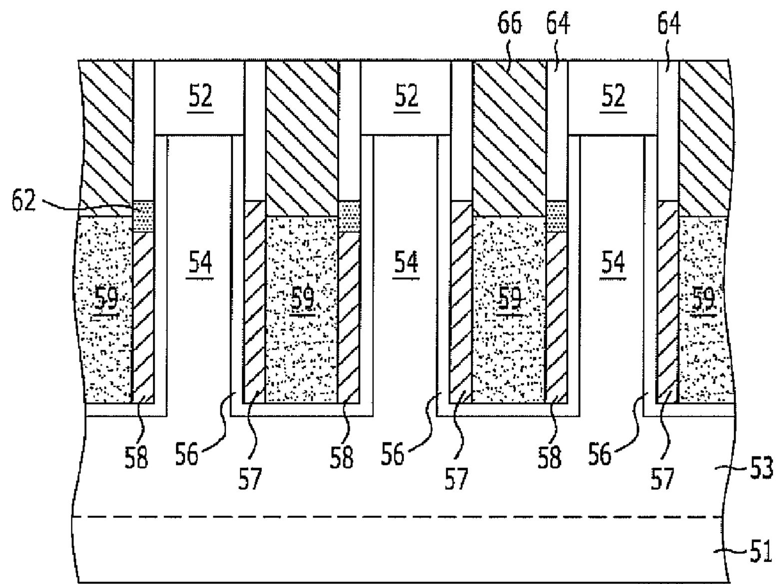


FIG. 11J

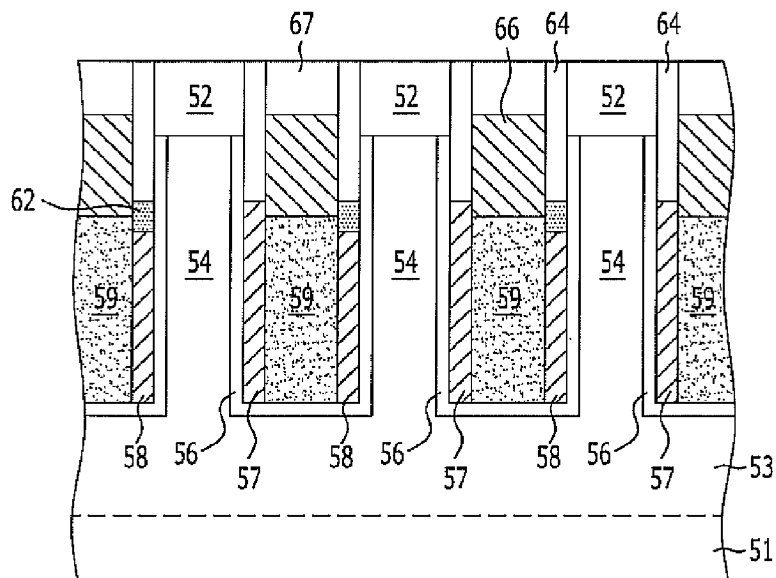


FIG. 12A

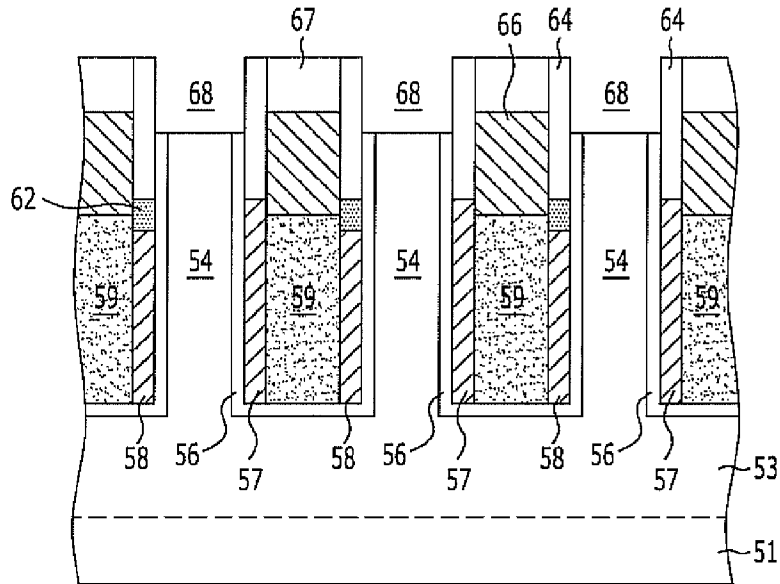


FIG. 12B

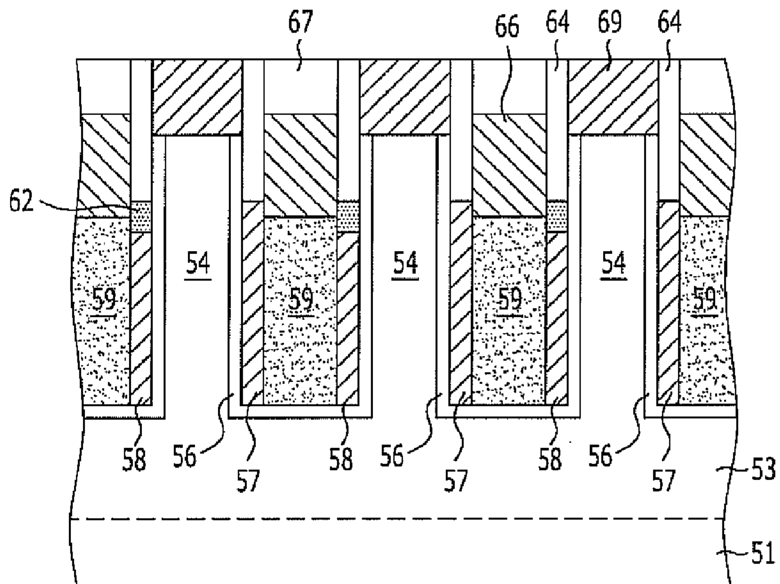


FIG. 12C

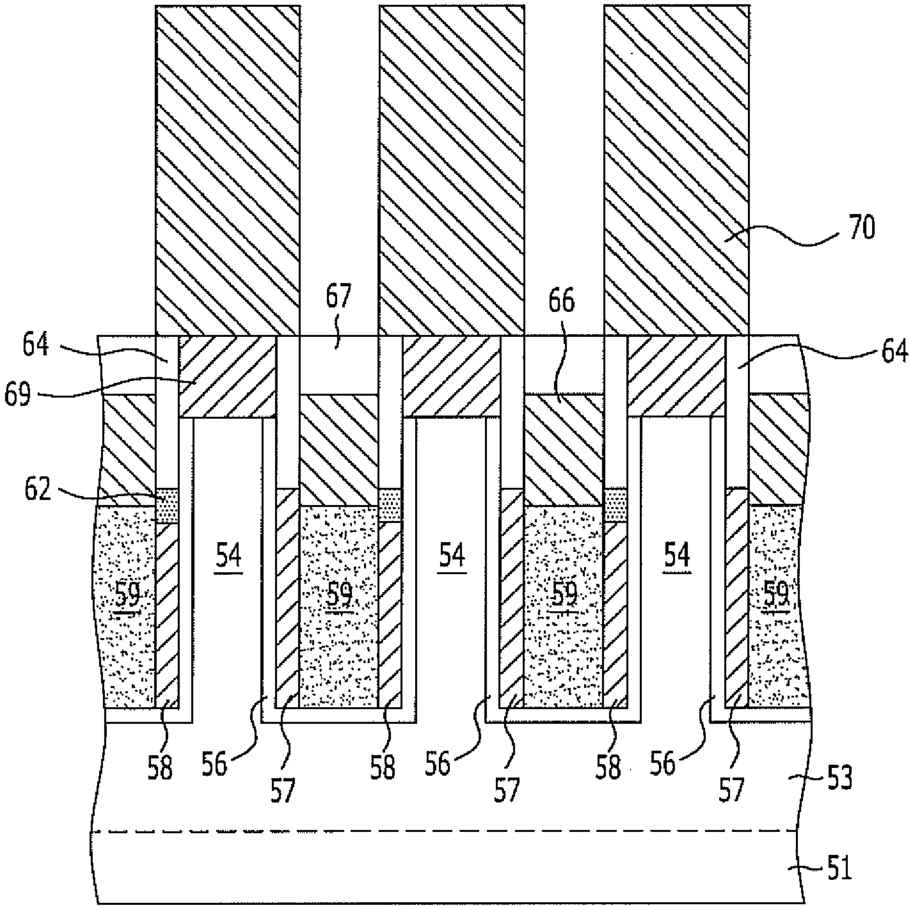


FIG. 13

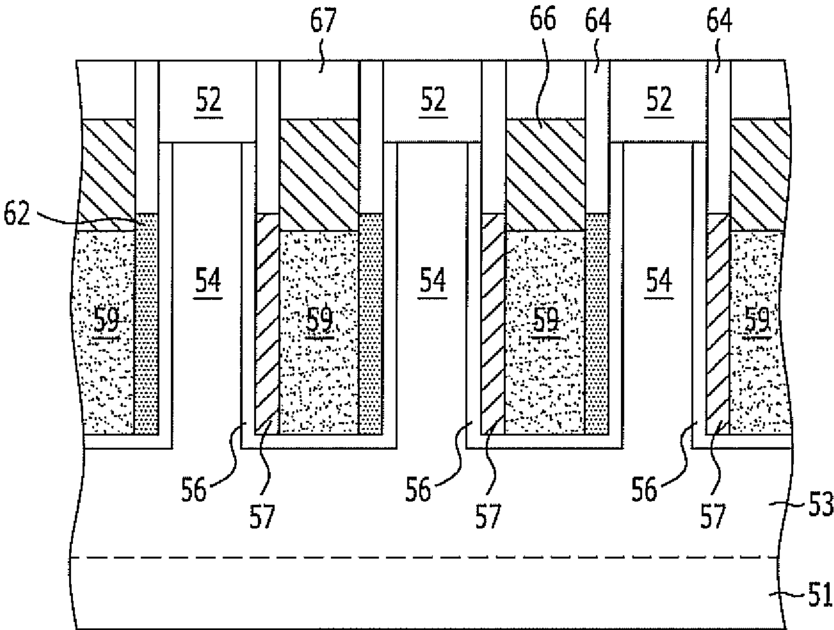


FIG. 14

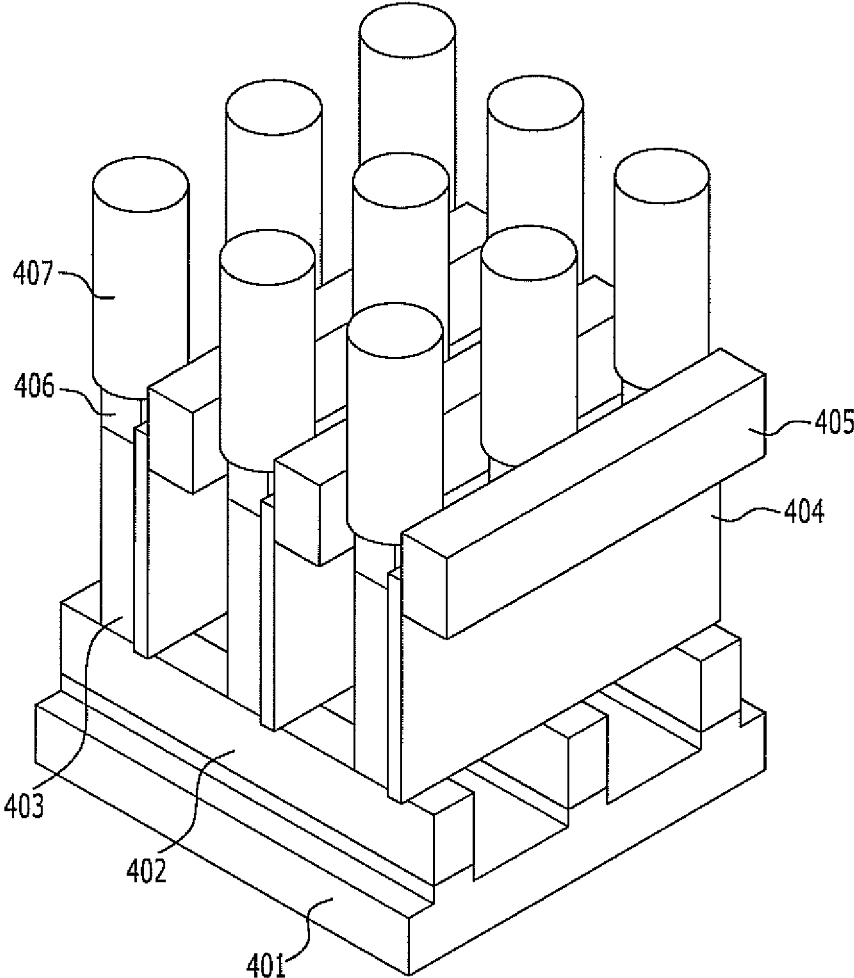


FIG. 15A

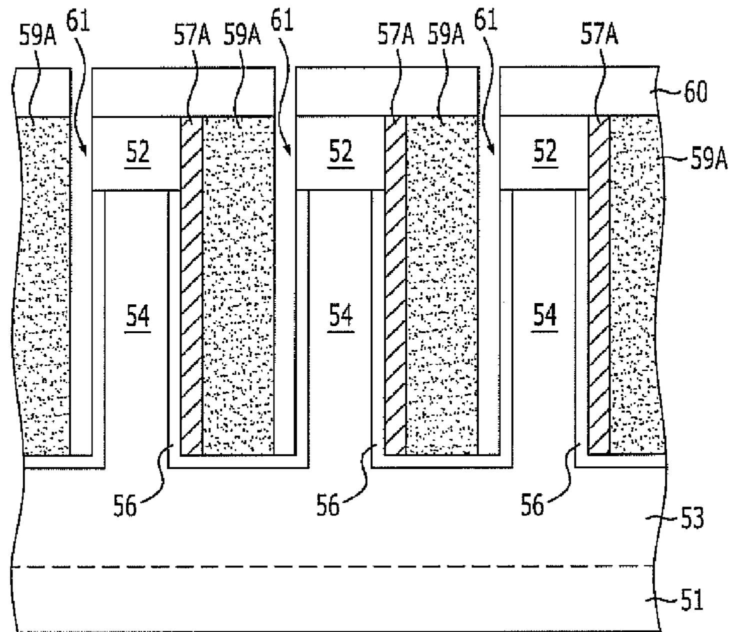


FIG. 15B

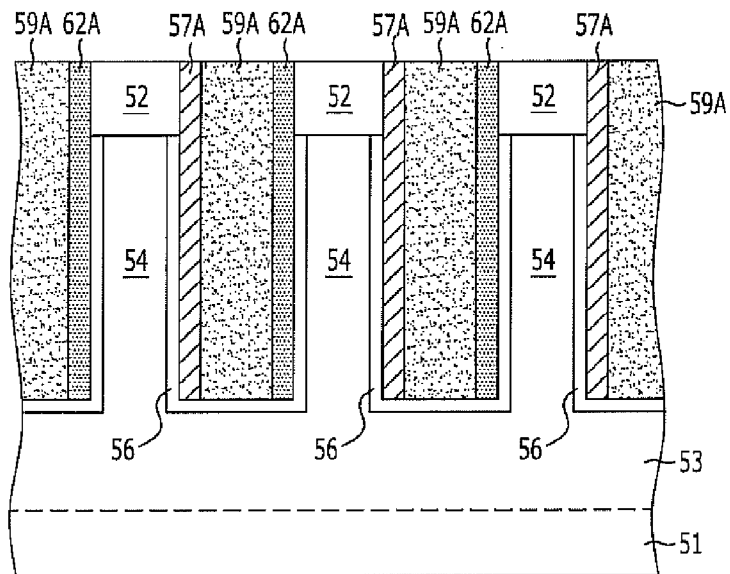


FIG. 15C

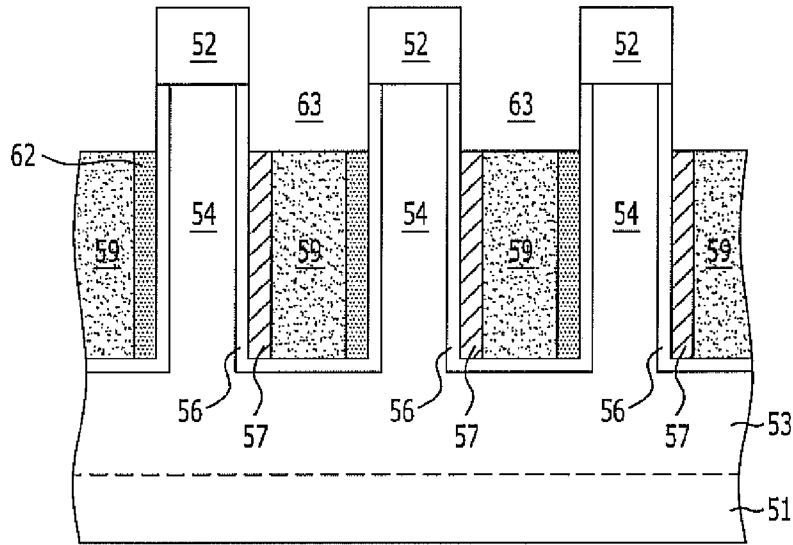


FIG. 15D

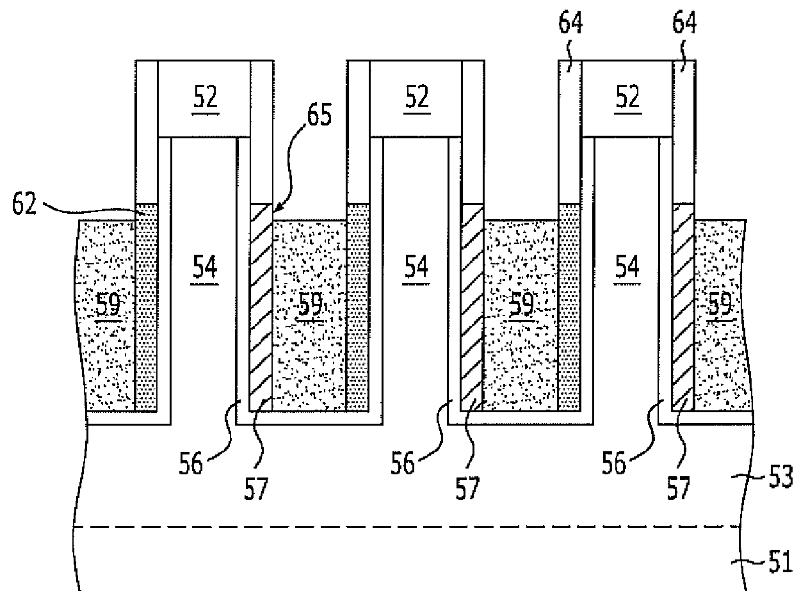


FIG. 15E

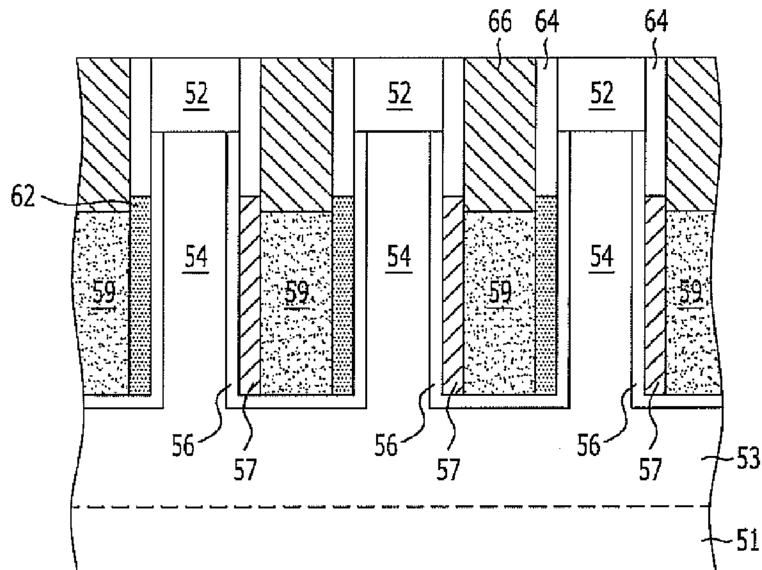


FIG. 15F

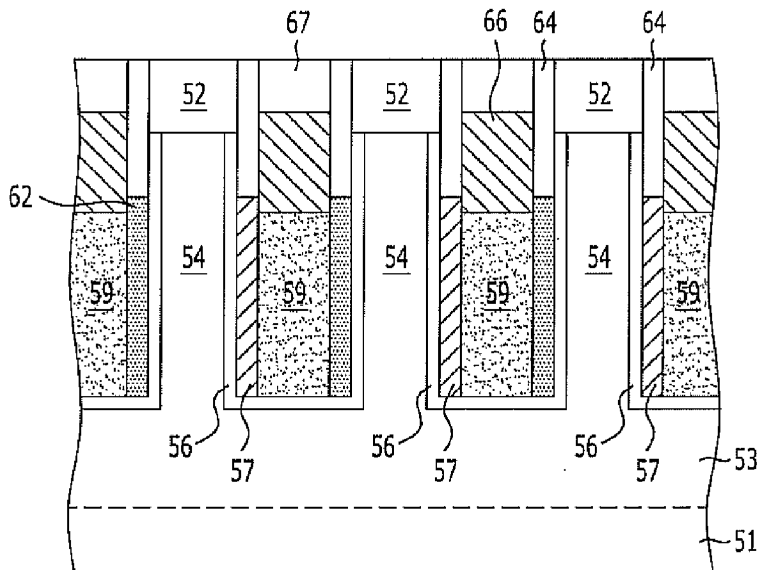


FIG. 16A

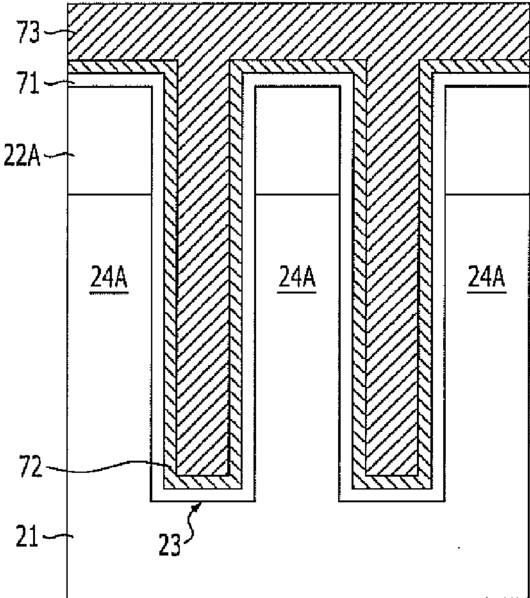


FIG. 16B

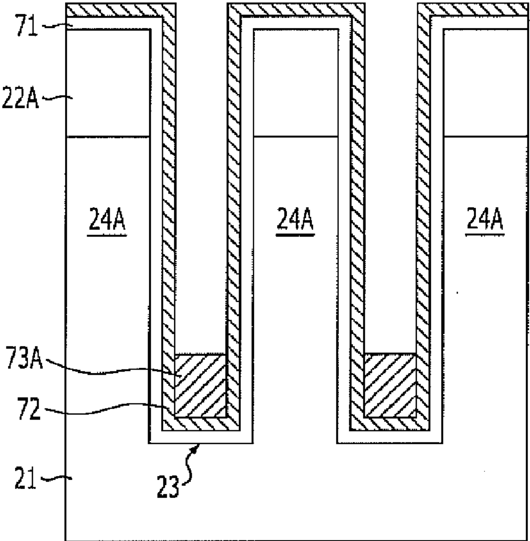


FIG. 16C

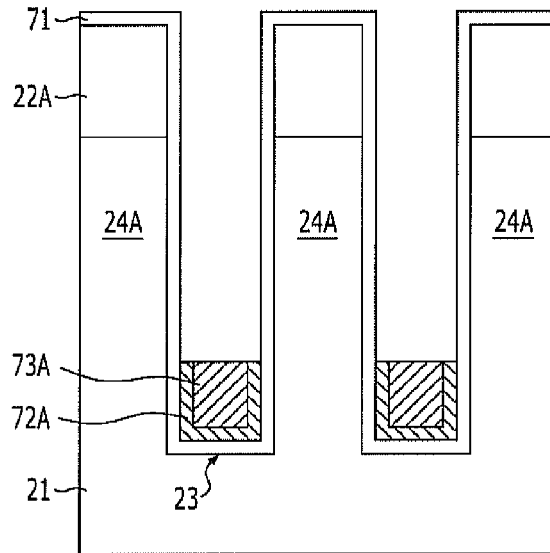


FIG. 16D

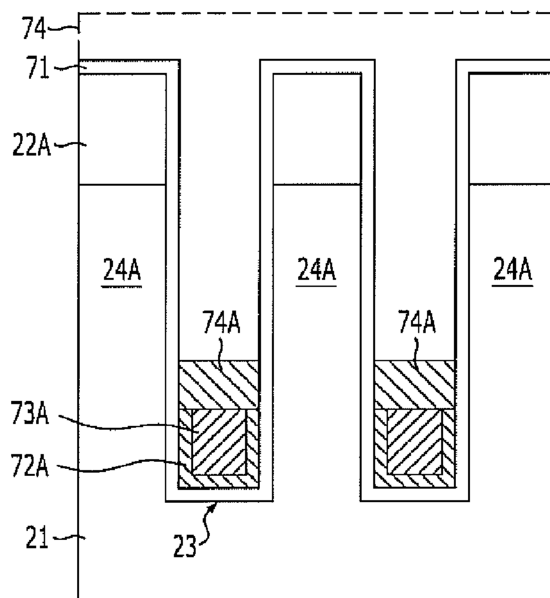


FIG. 16E

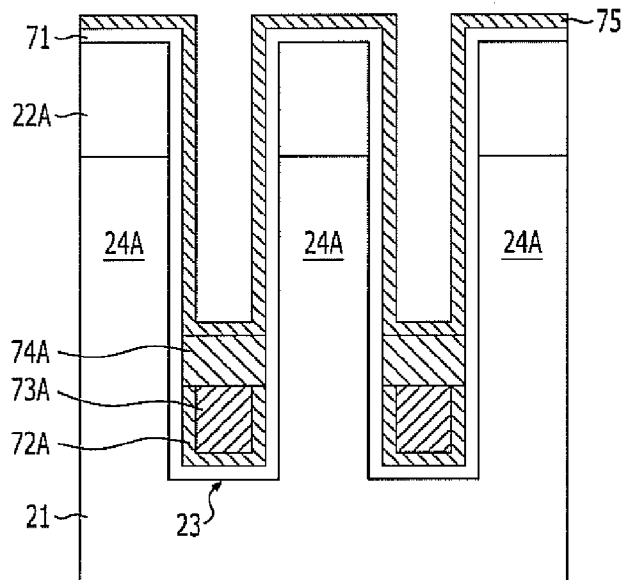


FIG. 16F

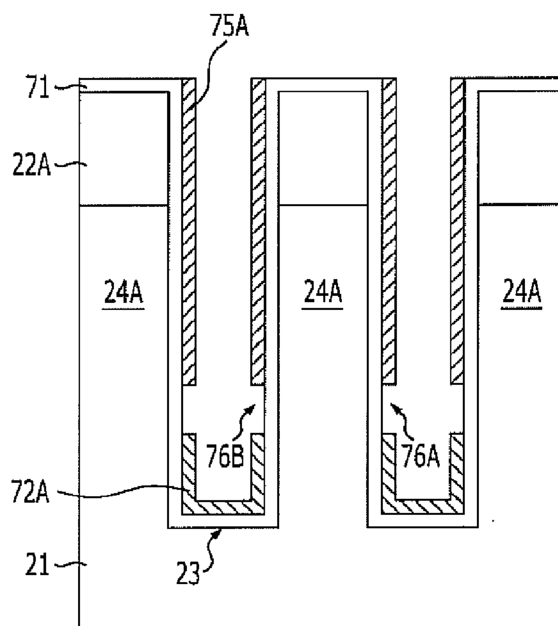


FIG. 16G

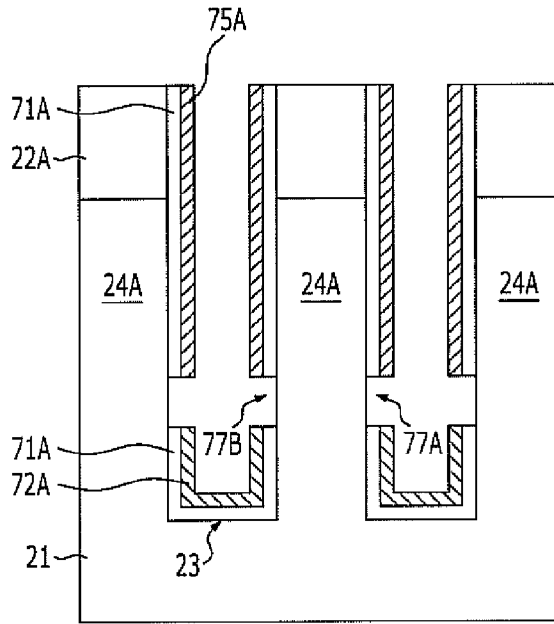


FIG. 16H

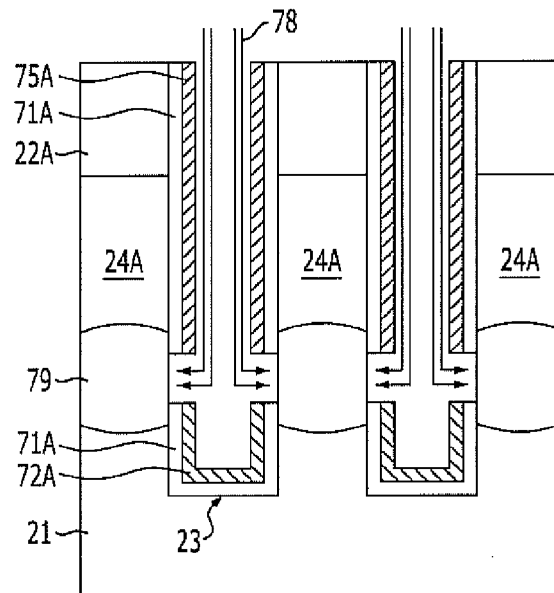


FIG. 16I

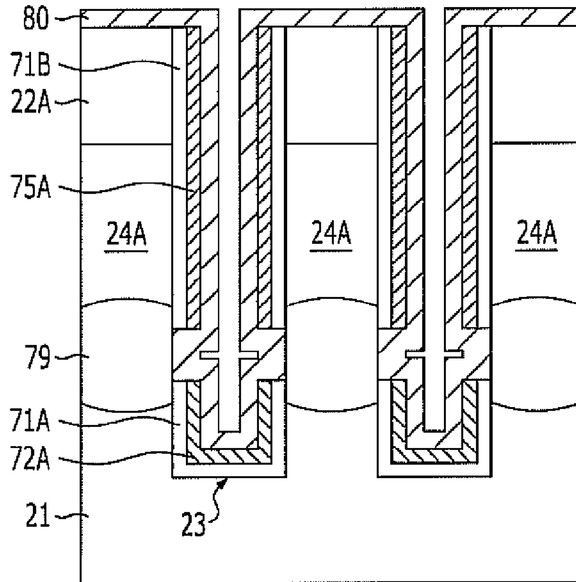


FIG. 16J

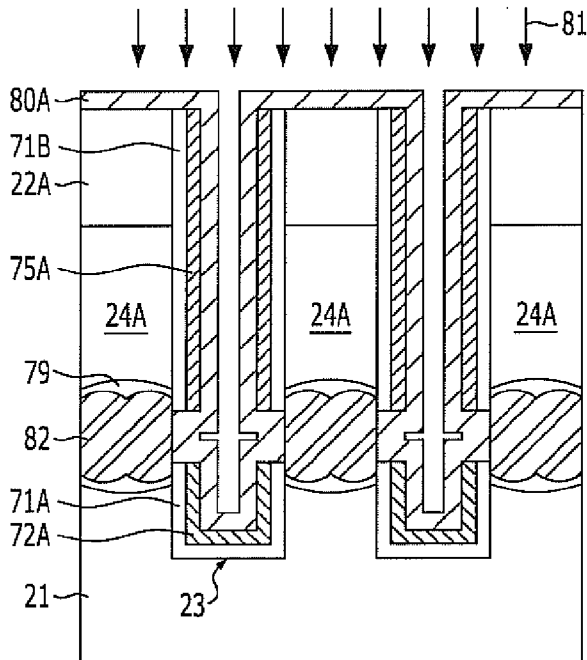
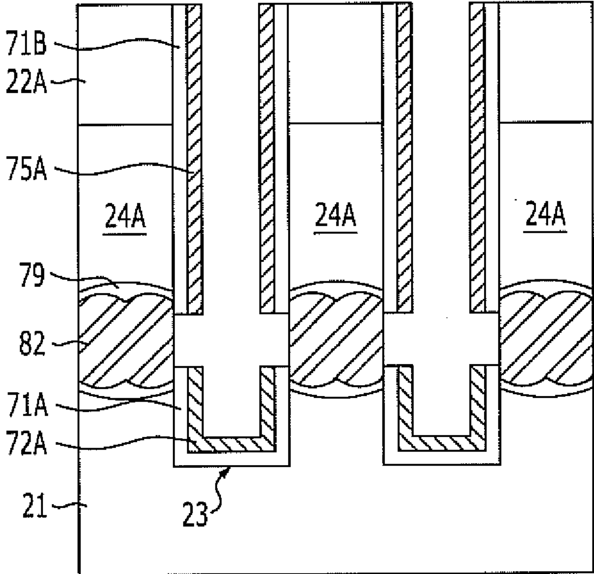


FIG. 16K



VERTICAL CHANNEL TRANSISTOR WITH SELF-ALIGNED GATE ELECTRODE AND METHOD FOR FABRICATING THE SAME

CROSS-REFERENCE TO RELATED APPLICATION

[0001] The present application claims priority of Korean Patent Application No. 10-2012-0058607, filed on May 31, 2012, which is incorporated herein by reference in its entirety.

BACKGROUND

[0002] 1. Field

[0003] Exemplary embodiments of the present invention relate to a semiconductor device, and more particularly, to a semiconductor device with a vertical channel transistor and a method for fabricating the same.

[0004] 2. Description of the Related Art

[0005] Most semiconductor devices include transistors. For example, in a memory device such as a DRAM, a memory cell includes a cell transistor such as a MOSFET. In general, in a MOSFET, source/drain regions are formed in a semiconductor substrate, and by this fact, a planar channel is formed between the source region and the drain region. Such a general MOSFET is referred to as a ‘planar channel transistor’.

[0006] As improvements in the degree of integration and performance are continuously required in a memory device, a MOSFET fabrication technology has a physical limit. For instance, as the size of a memory cell decreases, the size of a MOSFET decreases, and due to this fact, the channel length of the MOSFET cannot help but decrease. If the channel length of a MOSFET decreases, the characteristics of a memory device are likely to deteriorate due to various problems caused in that data retention characteristics deteriorate.

[0007] In consideration of these problems, a vertical channel transistor has been suggested. The vertical channel transistor (VCT) has a source region and a drain region which are formed in top and bottom portions of a pillar. The pillar serves as a channel, and a vertical gate electrode is formed on the sidewall of the pillar.

[0008] The vertical gate electrode is formed as an all-around gate structure or a double gate structure.

[0009] However, as the critical dimension decreases to 20 nm or below due to high integration, since a gap between pillars is narrow, a gate electrode cannot help but be formed thin. If the gate electrode is formed thin, resistance is likely to increase.

[0010] Also, since the gap between pillars is narrow, if electrodes are deposited to be thicker than a predetermined thickness, it is difficult to separate electrodes. If an over-etching process is performed to separate the electrodes, an underlying structure is likely to be etched and attacked in a region with a wide gap (for example, a pad region).

SUMMARY

[0011] Embodiments of the present invention are directed to a semiconductor device which has a vertical channel transistor capable of reducing the resistance of a vertical gate electrode, and a method for fabricating the same.

[0012] In accordance with an embodiment of the present invention, a method for fabricating vertical channel transistors may include: forming a plurality of pillars which have laterally opposing both sidewalls, over a substrate; forming a gate dielectric layer on both sidewalls of the pillars; forming first gate electrodes which cover any one sidewalls of the pillars and shield gate electrodes which cover the other sidewalls of the pillars and have a height lower than the first gate electrodes, over the gate dielectric layer; and forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes.

[0013] In accordance with another embodiment of the present invention, a method for fabricating vertical channel transistors may include: forming a plurality of pillars which have laterally opposing both sidewalls, over a substrate; forming a gate dielectric layer on both sidewalls of the pillars; forming first gate electrodes which cover any one sidewalls of both sidewalls of the pillars; and forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes.

[0014] In accordance with yet another embodiment of the present invention, a method for fabricating a semiconductor device may include: forming hard mask layer patterns over a semiconductor substrate; forming bodies by etching the semiconductor substrate using the hard mask layer patterns as an etch barrier; forming buried bit lines in the bodies; etching the hard mask layer patterns and upper portions of the bodies to form pillars which have laterally opposing both sidewalls; forming first gate electrodes on any one sidewalls of both sidewalls of the pillars; forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes; and forming storage nodes which are connected with the pillars.

[0015] In accordance with still another embodiment of the present invention, vertical channel transistors may include: a plurality of pillars vertically formed over a substrate and having laterally opposing both sidewalls; a gate dielectric layer formed on both sidewalls of the pillars; first gate electrodes formed on any one sidewalls of the pillars over the gate dielectric layer; and second gate electrodes, wherein each of the second gate electrode is connected with an upper portion of a corresponding first gate electrode.

[0016] In accordance with yet still another embodiment of the present invention, a semiconductor device may include: vertical channel transistors including a plurality of pillars which are formed on a substrate and have laterally opposing both sidewalls, a gate dielectric layer which is formed on both sidewalls of the pillars, and vertical gate electrodes which are formed on any one sidewalls of the pillars over the gate dielectric layer; capacitors including storage nodes which are connected with top portions of the pillars; and buried bit lines connected with bottom portions of the pillars.

BRIEF DESCRIPTION OF THE DRAWINGS

[0017] FIG. **1**A is a view illustrating vertical channel transistors in accordance with a first embodiment of the present invention.

[0018] FIG. **1**B is a plan view taken along the line A-A' of FIG. **1**A.

[0019] FIG. **1**C is a plan view taken along the line B-B' of FIG. **1**A.

[0020] FIG. **2** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the first embodiment of the present invention are applied.

[0021] FIGS. **3**A to **3**I are plan views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the first embodiment of the present invention.

[0022] FIGS. **4**A to **4**I are cross-sectional views taken along the line C-C' of FIGS. **3**A to **3**I.

[0023] FIGS. **5**A to **5**C are views explaining a method for fabricating a capacitor of the semiconductor device to which the vertical channel transistors in accordance with the first embodiment of the present invention are applied.

[0024] FIG. **6** is a view illustrating vertical channel transistors in accordance with a second embodiment of the present invention.

[0025] FIG. **7** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the second embodiment of the present invention are applied.

[0026] FIGS. **8**A to **8**E are views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the second embodiment of the present invention.

[0027] FIG. **9** is a view illustrating vertical channel transistors in accordance with a third embodiment of the present invention.

[0028] FIG. **10** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the third embodiment of the present invention are applied.

[0029] FIGS. **11**A to **11**J are views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the third embodiment of the present invention.

[0030] FIGS. **12**A to **12**C are views explaining a method for fabricating a capacitor of the semiconductor device to which the vertical channel transistors in accordance with the third embodiment of the present invention are applied.

[0031] FIG. **13** is a view illustrating vertical channel transistors in accordance with a fourth embodiment of the present invention.

[0032] FIG. **14** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the fourth embodiment of the present invention are applied.

[0033] FIGS. **15**A to **15**F are views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the fourth embodiment of the present invention.

[0034] FIGS. **16**A to **16**K are views explaining a method for forming a buried bit line of the semiconductor device to which the vertical channel transistors in accordance with the embodiments of the present invention are applied.

DETAILED DESCRIPTION

[0035] Exemplary embodiments of the present invention will be described below in more detail with reference to the accompanying drawings. The present invention may, however, be embodied in different forms and should not be construed as limited to the embodiments set forth herein. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the present invention to those skilled in the art. Throughout the disclosure, like reference numerals refer to like parts throughout the various figures and embodiments of the present invention.

[0036] The drawings are not necessarily to scale and in some instances, proportions may have been exaggerated in order to clearly illustrate features of the embodiments. When a first layer is referred to as being "on" a second layer or "on" a substrate, it not only refers to a case where the first layer is formed directly on the second layer or the substrate but also a case where a third layer exists between the first layer and the second layer or the substrate.

[0037] FIG. **1**A is a view illustrating vertical channel transistors in accordance with a first embodiment of the present invention. FIG. **1**B is a plan view taken along the line A-A' of FIG. **1**A, and FIG. **1**C is a plan view taken along the line B-B' of FIG. **1**A.

[0038] Referring to FIGS. **1**A to **1**C, vertical channel transistors in accordance with a first embodiment of the present invention may include pillars **26**, first gate electrodes **29**, shield gate electrodes **30**, and second gate electrodes **36**.

[0039] First, a plurality of pillars **26** are formed on a semiconductor substrate **21** to vertically project from the surface of the semiconductor substrate **21**. Bodies **24** may be further formed under the pillars **26**. The pillars **26** may vertically project from the surfaces of the bodies **24**. Hard mask layer patterns **22** may be formed on the pillars **26**. The plurality of pillars **26** may have a matrix arrangement. The pillars **26** may be quadrangular pillars each of which has a plurality of sidewalls. The pillars **26** may be arranged to be isolated by a dielectric layer **25** in a first direction Y, and the first and second sidewalls of the pillars **26** laterally opposing each other may be exposed in a second direction X. Each pillar **26** may have a source region, a drain region and a channel region (not numbered). The drain region may be formed in top portion of the pillar **26**, and the source region may be formed in bottom portion of the pillar **26**. The channel region may be formed between the drain region and the source region. The semiconductor substrate **21**, the bodies **24** and the pillars **26** include a silicon-containing substance. For example, a silicon substrate or a silicon-germanium substrate may be used. Accordingly, the pillar **26** may include a semiconductor pillar, a silicon pillar or a silicon-germanium pillar.

[0040] A gate dielectric layer **28** is formed on the first sidewalls and the second sidewalls of the pillars **26**. The gate dielectric layer **28** may include a silicon oxide or a high-k substance.

[0041] The first gate electrodes **29** are formed on the gate dielectric layer **28** to cover the first sidewalls of the pillars **26**. The shield gate electrodes **30** are formed on the gate dielectric layer **28** to cover the second sidewalls of the pillars **26**. The shield gate electrodes **30** are formed to have a height lower than the first gate electrodes **29**. The first gate electrodes **29** may be vertical gate electrodes.

[0042] The second gate electrodes **36** which are connected to the upper portions of the sidewalls of the first gate electrodes **29** are formed between the plurality of pillars **26**. The second gate electrodes **36** may serve as word lines. The second gate electrodes **36** may have shapes which are buried in the upper portions of the spaces defined between the plurality of pillars **26**. For example, the second gate electrodes **36** may be buried between the hard mask layer patterns **22**. A first dielectric layer **31** may be formed between the first gate electrodes **29** and the shield gate electrodes **30**, and a second dielectric layer **34** may be formed on the shield gate electrodes **30**. The first dielectric layer **31** and the second dielectric layer **34** may be recessed by a predetermined depth, and the second gate electrodes **36** may be formed on the first dielectric layer **31** and the second dielectric layer **34** which are recessed. The shield gate electrodes **30** neighboring the second gate electrodes **36** are isolated by the second dielectric layer **34**.

[0043] The first gate electrodes **29** and the shield gate electrodes **30** have line-shaped vertical gate structures which extend in the first direction Y. The second gate electrodes **36** have shapes which extend in the first direction Y in the same manner as the first gate electrodes **29**. The first gate electrodes **29** and the shield gate electrodes **30** may include a metal nitride or a low resistance metal. For example, the first gate electrodes **29** and the shield gate electrodes **30** may include TiN, TiAlN, WN, TaN, W, Al, Ru, Pt, Au, or the like. The second gate electrodes **36** may include W, Al, Ru, Pt, Au, or the like. The first gate electrodes **29** and the second gate electrodes **36** may be recessed by a predetermined depth, and a capping layer **37** may be additionally formed on the first gate electrodes **29** and the second gate electrodes **36** which are recessed.

[0044] According to FIGS. **1**A to **1**C, the vertical channel transistors in accordance with the first embodiment of the present invention have double gate structures in which the shield gate electrodes **30** and the first gate electrodes **29** are formed on both sidewalk of the pillars **26**. The first gate electrodes **29** become the gate electrodes of vertical channel transistors. Furthermore, as only the first gate electrodes **29** are formed on the sidewalls of the pillars **26**, the first gate electrodes **29** may be formed to have a substantial thickness. According to this fact, gate resistance may be reduced. The shield gate electrodes **30** function to shield electric fields by neighbor gates, that is, the neighbor first gate electrodes **29**, by which a neighbor gate effect may be minimized.

[0045] FIG. **2** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the first embodiment of the present invention are applied.

[0046] Referring to FIG. **2**, vertical channel transistors include first gate electrodes **104**, second gate electrodes **105**, and pillars **103**. Shield gate electrodes **106** are formed on the sidewalls of the pillars **103**. As buried bit lines **102** and capacitors **108** are connected to the vertical channel transistors, a semiconductor device such as a DRAM may be realized. The buried bit lines **102** may be electrically connected with the bottom portions of the pillars **103**. The buried bit lines **102** may be vertically formed on a semiconductor substrate **101** and may extend in a first direction. The first gate electrodes **104** and the second gate electrodes **105** may extend in a second direction perpendicularly crossing with the first direction. The capacitors **108** may be electrically connected with the top portions of the pillars **103**. Contact plugs **107** may be additionally formed between the capacitors **108** and the pillars **103**. While not shown, the capacitors **108** may include storage nodes, a dielectric layer and plate nodes. The vertical channel transistors may be applied not only to a memory such as a DRAM but also to a nonvolatile memory such as a flash memory.

[0047] FIGS. **3**A to **3**I are plan views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the first embodiment of the present invention. FIGS. **4**A to **4**I are cross-sectional views taken along the line C-C' of FIGS. **3**A to **3**I.

[0048] Referring to FIGS. **3**A and **4**A, hard mask layer patterns **22**A are formed on a semiconductor substrate **21**. The semiconductor substrate **21** includes a silicon-containing substance. For example, the semiconductor substrate **21** includes a silicon substrate or a silicon-germanium substrate. The hard mask layer patterns **22**A include a nitride such as a silicon nitride. Also, the hard mask layer patterns **22**A may include a silicon oxide or amorphous carbon. The hard mask layer patterns **22**A may have a multi-layered structure including an oxide or a nitride. For example, the hard mask layer patterns **22**A may be stacked in order of a hard mask (HM) nitride and a hard mask oxide. Also, the hard mask layer patterns **22**A may be stacked in order of a hard mask nitride, a hard mask oxide, a hard mask silicon oxynitride and hard mask carbon. In the case where a hard mask nitride is included, a pad oxide may be additionally formed between the semiconductor substrate **21** and the hard mask layer patterns **22**A. The pad oxide may include a silicon oxide. The hard mask layer patterns **22**A may be formed by being patterned using photoresist patterns after forming a hard mask layer. The hard mask layer patterns **22**A may be formed to extend in a second direction.

[0049] By etching the semiconductor substrate **21** by a predetermined depth using the hard mask layer patterns **22**A as an etch mask, a plurality of bodies **24**A are formed. The bodies **24**A are separated from one another by first trenches **23**. The plurality of bodies **24**A are separated from one another by the first trenches **23**. The bodies **24**A are formed to vertically extend from the surface of the semiconductor substrate **21**. The bodies **24**A have laterally opposing sidewalls. When viewed from the top, the bodies **24**A have linear shapes which are separated from one another by the first trenches **23**. For example, the bodies **24**A have linear structures which extend in the second direction.

[0050] By forming the bodies **24**A as described above, a plurality of structures including the bodies **24**A and the hard mask layer patterns **22**A are formed on the semiconductor substrate **21**. The plurality of structures are separated from one another by the first trenches **23**. While not shown, after defining the first trenches **23**, buried bit lines (BBL) may be additionally formed in the bodies **24**A using a substance such as a metal nitride. This will be described later.

[0051] Next, an interlayer dielectric layer **25**A is formed to fill the spaces between the bodies **24**A. The interlayer dielectric layer **25**A may include an oxide layer such as a silicon oxide. The interlayer dielectric layer **25**A may be planarized through CMP (chemical mechanical polishing) or the like until the surfaces of the hard mask layer patterns **22**A are exposed.

[0052] Referring to FIGS. **3**B and **4**B, photoresist patterns (not shown) are formed to extend in a direction crossing with the bodies **24**A, that is, a first direction. The hard mask layer patterns **22**A and the bodies **24**A are etched using the photoresist patterns as an etch barrier. According to this fact, a plurality of pillars **26** are formed. When etching the bodies **24**A, the interlayer dielectric layer **25**A and the hard mask layer patterns **22**A may also be etched. Accordingly, the hard mask layer patterns **22**A and the interlayer dielectric layer **25**A may remain as indicated by the reference numerals **22** and **25**, respectively.

[0053] The plurality of pillars **26** are separated from one another by second trenches **27**. The bodies **24**A remain as indicated by the reference numeral **24**, and the pillars **26** are formed on the bodies **24**. The plurality of pillars **26** may have a matrix arrangement. Each pillar **26** may have four sidewalls. The sidewalls of each pillar **26** which oppose each other in any one direction (the first direction in which the pillars **26** are separated from one another by the first trenches **23**) may contact the interlayer dielectric layer **25**. That is to say, the interlayer dielectric layer **25** is formed between the pillars **26** which are arranged in the first direction. The other laterally

opposing sidewalls (hereinafter, referred to as 'first sidewalls and second sidewalls') of the pillars **26** which are arranged in the second direction are exposed by the second trenches **27**. The second trenches **27** extend in the direction crossing with the first trenches **23**, and may have a depth shallower than the first trenches **23**. Accordingly, the pillars **26** are formed in a plural number on each body **24**. The plurality of bodies **24** are separated from one another by the first trenches **23**, and the plurality of pillars **26** are separated from one another by the second trenches **27**.

[0054] Referring to FIGS. **3**C and **4**C, a gate dielectric layer **28** is formed on the first sidewalls and the second sidewalls of the pillars **26**. The gate dielectric layer **28** may be formed through oxidation such as thermal oxidation or plasma oxidation. The gate dielectric layer **28** may be formed on the entire surface through chemical vapor deposition (CVD) or atomic layer deposition (ALD). The gate dielectric layer **28** may include a silicon oxide, a high-k substance, or the like.

[0055] Next, first gate electrodes **29** and preliminary shield gate electrodes **30**A are respectively formed on the first sidewalls and the second sidewalls of the pillars **26** which are formed with the gate dielectric layer **28**. The preliminary shield gate electrodes **30**A and the first gate electrodes **29** may extend in the first direction. In order to form the preliminary shield gate electrodes **30**A and the first gate electrodes **29**, an etch-back process may be performed after forming a first conductive layer on the entire surface. According to this fact, the preliminary shield gate electrodes **30**A and the first gate electrodes **29** may be simultaneously formed. The first conductive layer may include an oxide, a metal nitride with low reactivity or a low resistance metal. For example, the preliminary shield gate electrodes **30**A may include TIN, TiAlN, WN, TaN, W, Al, Ru, Pt, Au, or the like. Hereafter, in the present embodiment, the first conductive layer may be formed using a titanium nitride (TiN).

[0056] Referring to FIGS. **3**D and **4**D, a first dielectric layer **31**A is formed to fill the spaces between the pillars **26** which are formed with the first gate electrodes **29** and the preliminary shield gate electrodes **30**A. The first dielectric layer **31**A may include an oxide such as a silicon oxide. The first dielectric layer **31**A may be planarized through CMP or the like until the surfaces of the hard mask layer patterns **22** are exposed.

[0057] Referring to FIGS. **3**E and **4**E, photoresist patterns **32** are formed. The photoresist patterns **32** may have shapes which expose the upper surfaces of the preliminary shield gate electrodes **30**A.

[0058] The preliminary shield gate electrodes **30**A are etched by a predetermined depth using the photoresist patterns **32** as an etch barrier. According to this fact, shield gate electrodes **30** are formed, and gaps **33** are defined on the shield gate electrodes **30**.

[0059] By forming the shield gate electrodes **30** as described above, double gate structures including the shield gate electrodes **30** and the first gate electrodes **29** are formed in a self-aligned manner on the first sidewalls and the second sidewalls of the pillars **26**. The shield gate electrodes **30** and the first gate electrodes **29** have a height difference. While the first gate electrodes **29** serve as the gate electrodes of vertical channel transistors, the shield gate electrodes **30** do not serve as gate electrodes. The shield gate electrodes **30** may perform a function of shielding electric fields by the neighbor first gate electrodes **29**, by which it is possible to minimize a neighbor gate effect.

[0060] Referring to FIGS. **3**F and **4**F, a second dielectric layer **34**A is formed to fill the gaps **33**. The second dielectric layer **34**A may include an oxide such as a silicon oxide. Also, the second dielectric layer **34**A may include a nitride such as a silicon nitride. The second dielectric layer **34**A may be planarized through CMP or the like until the surfaces of the hard mask layer patterns **22** are exposed. The second dielectric layer **34**A is formed on the shield gate electrodes **30**.

[0061] Referring to FIGS. **3**G and **4**G, the first dielectric layer **31**A and the second dielectric layer **34**A are recessed by a predefined depth. According to this fact, recesses **35** are defined. The depth of the recesses **35** may be the same as the height of the hard mask layer patterns **22**. The depth of the recesses **35** may be controlled to be lower than the upper surfaces of the pillars **26**. The recesses **35** may be defined between neighboring hard mask layer patterns **22**. The upper portions of the sidewalls of the first gate electrodes **29** are exposed due to defining the recesses **35**, and the first and second dielectric layers **31** and **34** remain on the bottoms of the recesses **35**. The recesses **35** are defined such that the shield gate electrodes **30** are not exposed.

[0062] Referring to FIGS. **3**H and **4**H, second gate electrodes **36** are formed to fill the recesses **35**. The second gate electrodes **36** may extend in the first direction. In order to form the second gate electrodes **36**, an etch-back process may be performed after forming a second conductive layer on the entire surface. The second conductive layer may include W, Al, Ru, Pt, Au, or the like. Hereafter, the second conductive layer may be formed of tungsten (W). The second gate electrodes **36** may have structures which are buried in the recesses **35**.

[0063] The second gate electrodes **36** are connected with the first gate electrodes **29**, and the first and second gate electrodes **29** and **36** and the shield gate electrodes **30** may be isolated by the first and second dielectric layers **31** and **34**.

[0064] Referring to FIGS. **3**I and **4**I, the first and second gate electrodes **29** and **36** are recessed by a predetermined depth. A capping layer **37** is formed to fill recessed regions. The capping layer **37** may include an oxide layer such as a silicon oxide. By forming the capping layer **37** in this way, the first and second gate electrodes **29** and **36** are isolated from surrounding structures.

[0065] FIGS. **5**A to **5**C are views explaining a method for fabricating a capacitor of the semiconductor device to which the vertical channel transistors in accordance with the first embodiment of the present invention are applied.

[0066] Referring to FIG. **5**A, contact holes **38** are defined by removing the hard mask layer patterns **22**. Since the interlayer dielectric layer **25** and the capping layer **37** are a silicon oxide and the hard mask layer patterns **22** are a silicon nitride, the hard mask layer patterns **22** may be removed through a wet etching using a phosphoric acid. According to this fact, the contact holes **38** are defined in a self-defined manner by the capping layer **37** and the interlayer dielectric layer **25**. The upper surfaces of the pillars **26** are exposed on the bottoms of the contact holes **38**.

[0067] Referring to FIG. **5**B, spacers **39** are formed to surround the sidewalls of the contact holes **38**. The spacers **39** may include an oxide such as a silicon oxide. In order to form the spacers **39**, an etch-back process may be performed after depositing a silicon oxide.

[0068] Contact plugs **40** are formed to be buried in the contact holes **38**. The contact plugs **40** may include a polysilicon, a metal or the like. For example, after depositing a

polysilicon to fill the contact holes **38**, a planarization process may be performed. The spacers **39** surround the sidewalls of the contact plugs **40**. While not shown, ion implantation for forming sources/drains may be carried out before forming the contact plugs **40**.

[0069] Referring to FIG. **5**C, storage nodes **41** of capacitors are formed on the contact plugs **40**. The storage nodes **41** may have pillar shapes. In another embodiment, the storage nodes **41** may have cylinder shapes. As a method for forming the storage nodes **41**, well-known methods may be adopted. For example, after forming a mold layer (not shown), open parts are formed by etching the mold layer, and the storage nodes **41** are formed in the open parts. Then, the mold layer is removed through a full dip-out process.

[0070] While not shown, supporters for supporting the outer walls of the storage nodes **41** may be additionally formed. For example, a substance for supporters is formed on the mold layer, and supporters may be formed by partially etching the substance for supporters before performing the full dip-out process. Furthermore, a dielectric layer and plate nodes may be additionally formed on the storage nodes **41**.

[0071] FIG. **6** is a view illustrating vertical channel transistors in accordance with a second embodiment of the present invention.

[0072] Referring to FIG. **6**, vertical channel transistors in accordance with a first embodiment of the present invention may include pillars **26**, first gate electrodes **29**, and second gate electrodes **36**.

[0073] First, a plurality of pillars **26** are formed on a semiconductor substrate **21** to vertically project from the surface of the semiconductor substrate **21**. Bodies **24** may be further formed under the pillars **26**. The pillars **26** may vertically project from the surfaces of the bodies **24**. Hard mask layer patterns **22** may be formed on the pillars **26**. The plurality of pillars **26** may have a matrix arrangement. The pillars **26** may be quadrangular pillars each of which has a plurality of sidewalls. The pillars **26** may be arranged to be isolated by an interlayer dielectric layer in a first direction Y, and the first and second sidewalls of the pillars **26** laterally opposing each other may be exposed in a second direction X. Each pillar **26** may have a source region, a drain region and a channel region (not numbered). The drain region may be formed in top portion of the pillar **26**, and the source region may be formed in bottom portion of the pillar **26**. The channel region may be formed between the drain region and the source region. The semiconductor substrate **21**, the bodies **24** and the pillars **26** include a silicon-containing substance. For example, a silicon substrate or a silicon-germanium substrate may be used. Accordingly, the pillar **26** may include a semiconductor pillar, a silicon pillar or a silicon-germanium pillar.

[0074] A gate dielectric layer **28** is formed on the first sidewalls and the second sidewalls of the pillars **26**. The gate dielectric layer **28** may include a silicon oxide or a high-k substance.

[0075] The first gate electrodes **29** are formed on the gate dielectric layer **28** to cover the first sidewalls of the pillars **26**. The first gate electrodes **29** are vertical gate electrodes. The first gate electrodes **29** are not formed on the second sidewalls of the pillars **26**. Also, unlike the first embodiment, shield gate electrodes to cover the second sidewalls are not formed.

[0076] The second gate electrodes **36** which are connected to the upper portions of the sidewalls of the first gate electrodes **29** are formed between the plurality of pillars **26**. The second gate electrodes **36** may serve as word lines. The second gate electrodes **36** may have shapes which are buried in the upper portions of the spaces defined between the plurality of pillars **26**. For example, the second gate electrodes **36** may be buried between the hard mask layer patterns **22**. A first dielectric layer **31** and a second dielectric layer **34** may be formed between the first gate electrodes **29** and adjoining pillars **26**. The first dielectric layer **31** and the second dielectric layer **34** may be recessed by a predetermined depth, and the second gate electrodes **36** may be formed on the first dielectric layer **31** and the second dielectric layer **34** which are recessed.

[0077] The first gate electrodes **29** have line-shaped vertical gate structures which extend in the first direction Y. The second gate electrodes **36** have shapes which extend in the first direction Y in the same manner as the first gate electrodes **29**. The first gate electrodes **29** may include a metal nitride or a low resistance metal. For example, the first gate electrodes **29** may include TiN, TiAlN, WN, TaN, W, Al, Ru, Pt, Au, or the like. The second gate electrodes **36** may include W, Al, Ru, Pt, Au, or the like. The first gate electrodes **29** and the second gate electrodes **36** may be recessed by a predetermined depth, and a capping layer **37** may be additionally formed on the first gate electrodes **29** and the second gate electrodes **36** which are recessed.

[0078] According to FIG. **6**, the vertical channel transistors in accordance with the second embodiment of the present invention have single gate structures in which the first gate electrodes **29** are formed on only one sidewalls of the pillars **26**. The first gate electrodes **29** become the gate electrodes of vertical channel transistors. Furthermore, as only the first gate electrodes **29** are formed on the sidewalls of the pillars **26**, the first gate electrodes **29** may be formed to have a substantial thickness. According to this fact, gate resistance may be reduced. In particular, because only the first gate electrodes **29** are formed without forming shield gate electrodes, a neighbor gate effect may be originally prevented.

[0079] FIG. **7** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the second embodiment of the present invention are applied.

[0080] Referring to FIG. **7**, vertical channel transistors include first gate electrodes **204**, second gate electrodes **205**, and pillars **203**. As buried bit lines **202** and capacitors **207** are connected to the vertical channel transistors, a semiconductor device such as a DRAM may be realized. The buried bit lines **202** may be electrically connected with the bottom portions of the pillars **203**. The buried bit lines **202** may be vertically formed on a semiconductor substrate **201** and may extend in a first direction. The first gate electrodes **204** and the second gate electrodes **205** may extend in a second direction perpendicularly crossing with the first direction. The capacitors **207** may be electrically connected with the top portions of the pillars **203**. Contact plugs **206** may be additionally formed between the capacitors **207** and the pillars **203**. While not shown, the capacitors **207** may include storage nodes, a dielectric layer and plate nodes. The vertical channel transistors may be applied not only to a memory such as a DRAM but also to a nonvolatile memory such as a flash memory.

[0081] FIGS. **8**A to **8**E are views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the second embodiment of the present invention. Unlike the first embodiment, when defining gaps, shield

gate electrodes are entirely removed. Hereinbelow, reference will be made to FIGS. **4**A to **4**D for processes before defining the gaps.

[0082] Referring to FIG. **8**A, photoresist patterns **32** are formed. The photoresist patterns **32** may have shapes which expose the upper surfaces of the preliminary shield gate electrodes **30**A.

[0083] The exposed preliminary shield gate electrodes **30**A are entirely removed using the photoresist patterns **32** as an etch barrier. According to this fact, gaps **33** are defined. Unlike the first embodiment, in the second embodiment, as the preliminary shield gate electrodes **30**A are entirely removed, shield gate electrodes are not formed. The preliminary shield gate electrodes **30**A removed in this way may be sacrificial gate electrodes.

[0084] By entirely removing the preliminary shield gate electrodes **30**A as described above, only the first gate electrodes **29** remain on the one sidewalls of the pillars **26**.

[0085] The first gate electrodes **29** serve as the gate electrodes of the vertical channel transistors. By not forming shield gate electrodes, a neighbor gate effect by neighbor gates may be originally prevented.

[0086] Referring to FIG. **8**B, a second dielectric layer **34**A is formed to fill the gaps **33**. The second dielectric layer **34**A may include an oxide such as a silicon oxide. Also, the second dielectric layer **34**A may include a nitride such as a silicon nitride. The second dielectric layer **34**A may be planarized through CMP or the like until the surfaces of the hard mask layer patterns **22** are exposed.

[0087] Referring to FIG. **8**C, the first dielectric layer **31**A and the second dielectric layer **34**A are recessed by a predefined depth. According to this fact, recesses **35** are defined. The depth of the recesses **35** may be the same as the height of the hard mask layer patterns **22**. The depth of the recesses **35** may be controlled to be lower than the upper surfaces of the pillars **26**. The recesses **35** may be defined between neighboring hard mask layer patterns **22**. The upper portions of the sidewalls of the first gate electrodes **29** are exposed due to defining the recesses **35**, and the first and second dielectric layers **31** and **34** remain on the bottoms of the recesses **35**.

[0088] Referring to FIG. **8**D, second gate electrodes **36** are formed to fill the recesses **35**. The second gate electrodes **36** may extend in the first direction. In order to form the second gate electrodes **36**, an etch-back process may be performed after forming a second conductive layer on the entire surface. The second conductive layer may include W, Al, Ru, Pt, Au, or the like. The second conductive layer may be formed of tungsten (W). The second gate electrodes **36** may have structures which are buried in the recesses **35**.

[0089] The second gate electrodes **36** are connected with the upper portions of the sidewalls of the first gate electrodes **29**, and the first and second gate electrodes **29** and **36** and adjoining pillars **26** may be isolated by the first and second dielectric layers **31** and **34**.

[0090] Referring to FIG. **8**E, the first and second gate electrodes **29** and **36** are recessed by a predetermined depth. A capping layer **37** is formed to fill recessed regions. The capping layer **37** may include an oxide layer such as a silicon oxide. By forming the capping layer **37** in this way, the first and second gate electrodes **29** and **36** are isolated from surrounding structures.

[0091] Contact plugs and capacitors are subsequently formed. Reference may be made to FIGS. **5**A to **5**C for a method for forming the contact plugs and the capacitors.

[0092] FIG. **9** is a view illustrating vertical channel transistors in accordance with a third embodiment of the present invention.

[0093] Referring to FIG. **9**, vertical channel transistors in accordance with a third embodiment of the present invention may include pillars **54**, first gate electrodes **57**, shield gate electrodes **58**, and second gate electrodes **66**.

[0094] First, a plurality of pillars **54** are formed on a semiconductor substrate **51** to vertically project from the surface of the semiconductor substrate **51**. Bodies **53** may be further formed under the pillars **54**. The pillars **54** may vertically project from the surfaces of the bodies **53**. The plurality of pillars **54** may have a matrix arrangement. The pillars **54** may be quadrangular pillars each of which has a plurality of sidewalls. The pillars **54** may be arranged to be isolated by an interlayer dielectric layer (not shown) in a first direction Y, and the first and second sidewalls of the pillars **54** laterally opposing each other may be exposed in a second direction X. Each pillar **54** may have a source region, a drain region and a channel region (not numbered). The drain region may be formed in top portion of the pillar **54**, and the source region may be formed in bottom portion of the pillar **54**. The channel region may be formed between the drain region and the source region. The semiconductor substrate **51**, the bodies **53** and the pillars **54** include a silicon-containing substance. For example, a silicon substrate or a silicon-germanium substrate may be used. Accordingly, the pillar **54** may include a semiconductor pillar, a silicon pillar or a silicon-germanium pillar.

[0095] A gate dielectric layer **56** is formed on the first sidewalls and the second sidewalls of the pillars **54**. The gate dielectric layer **56** may include a silicon oxide or a high-k substance.

[0096] The first gate electrodes **57** are formed on the gate dielectric layer **56** to cover the first sidewalls of the pillars **54**. The first gate electrodes **57** may be vertical gate electrodes. The shield gate electrodes **58** are formed to cover the second sidewalls of the pillars **54**. The shield gate electrodes **58** may be formed to have a height lower than the first gate electrodes **57**. Also, the first gate electrodes **57** and the shield gate electrodes **58** may be formed to have heights lower than the height of the pillars **54**.

[0097] The second gate electrodes **66** which are connected to the upper portions of the sidewalls of the first gate electrodes **57** are formed between the plurality of pillars **54**. The second gate electrodes **66** may serve as word lines. The second gate electrodes **66** may have shapes which are buried in the upper portions of the spaces defined between the plurality of pillars **54**. For example, the second gate electrodes **66** may be buried between hard mask layer patterns **52**. A first dielectric layer **59** may be formed between the first gate electrodes **57** and the shield gate electrodes **58**, and a second dielectric layer **62** may be formed on the shield gate electrodes **58**. The first dielectric layer **59** and the second dielectric layer **62** may be recessed by predetermined depths, and the second gate electrodes **66** may be formed on the first dielectric layer **59** which is recessed. The shield gate electrodes **58** neighboring the second gate electrodes **66** are isolated by the second dielectric layer **62**. Spacers **64** may be formed on the second dielectric layer **62** and the first gate electrodes **57**. The second gate electrodes **66** may be isolated from the surrounding structures by the spacers **64**. A capping layer **67** may be additionally formed on the second gate electrodes **66**.

[0098] The first gate electrodes **57** and the shield gate electrodes **58** have line-shaped vertical gate structures which

extend in the first direction Y. The second gate electrodes **66** have shapes which extend in the first direction Y in the same manner as the first gate electrodes **57**. The first gate electrodes **57** and the shield gate electrodes **58** may include a metal nitride or a low resistance metal. For example, the first gate electrodes **57** and the shield gate electrodes **58** may include TiN, TiAlN, WN, TaN, W, Al, Ru, Pt, Au, or the like. The second gate electrodes **66** may include W, Al, Ru, Pt, Au, or the like.

[0099] According to FIG. **9**, the vertical channel transistors in accordance with the third embodiment of the present invention have double gate structures in which the shield gate electrodes **58** and the first gate electrodes **57** are formed on both sidewalls of the pillars **54**. The first gate electrodes **57** become the gate electrodes of vertical channel transistors. Furthermore, as only the first gate electrodes **57** are formed on the sidewalls of the pillars **54**, the first gate electrodes **57** may be formed to have a substantial thickness. According to this fact, gate resistance may be reduced. The shield gate electrodes **58** function to shield electric fields by neighbor gates, by which a neighbor gate effect may be minimized.

[0100] FIG. **10** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the third embodiment of the present invention are applied.

[0101] Referring to FIG. **10**, vertical channel transistors include first gate electrodes **304**, second gate electrodes **305**, and pillars **303**. Shield gate electrodes **306** are formed on the sidewalls of the pillars **303**. As buried bit lines **302** and capacitors **308** are connected to the vertical channel transistors, a semiconductor device such as a DRAM may be realized. The buried bit lines **302** may be electrically connected with the bottom portions of the pillars **303**. The buried bit lines **302** may be vertically formed on a semiconductor substrate **301** and may extend in a first direction. The first gate electrodes **304** and the second gate electrodes **305** may extend in a second direction perpendicularly crossing with the first direction. The capacitors **308** may be electrically connected with the top portions of the pillars **303**. Contact plugs **307** may be additionally formed between the capacitors **308** and the pillars **303**. While not shown, the capacitors **308** may include storage nodes, a dielectric layer and plate nodes. The vertical channel transistors may be applied not only to a memory such as a DRAM but also to a nonvolatile memory such as a flash memory.

[0102] FIGS. **11**A to **11**J are views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the third embodiment of the present invention.

[0103] Referring to FIG. **11**A, hard mask layer patterns **52**A are formed on a semiconductor substrate **51**. The semiconductor substrate **51** includes a silicon-containing substance. For example, the semiconductor substrate **51** includes a silicon substrate or a silicon-germanium substrate. The hard mask layer patterns **52**A include a nitride such as a silicon nitride. Also, the hard mask layer patterns **52**A may include a silicon oxide or amorphous carbon. The hard mask layer patterns **52**A may have a multi-layered structure including an oxide or a nitride. For example, the hard mask layer patterns **52**A may be stacked in order of a hard mask (HM) nitride and a hard mask oxide. Also, the hard mask layer patterns **52**A may be stacked in order of a hard mask nitride, a hard mask oxide, a hard mask silicon oxynitride and hard mask carbon. In the case where a hard mask nitride is included, a pad oxide may be additionally formed between the semiconductor substrate **51** and the hard mask layer patterns **52**A. The pad oxide may include a silicon oxide. The hard mask layer patterns **52**A may be formed by being patterned using photoresist patterns after forming a hard mask layer. The hard mask layer patterns **52**A may be formed to extend in a second direction.

[0104] By etching the semiconductor substrate **51** by a predetermined depth using the hard mask layer patterns **52**A as an etch mask, a plurality of bodies **53**A are formed. The bodies **53**A are separated from one another by first trenches (not shown). The plurality of bodies **53**A are separated from one another by the first trenches. The bodies **53**A are formed to vertically extend from the surface of the semiconductor substrate **51**. The bodies **53**A have laterally opposing sidewalls. When viewed from the top, the bodies **53**A have linear shapes which are separated from one another by the first trenches. For example, the bodies **53**A have linear structures which extend in the second direction. Reference may be made to the first trenches **23** of FIG. **3**A for the first trenches.

[0105] By forming the bodies **53**A as described above, a plurality of structures including the bodies **53**A and the hard mask layer patterns **52**A are formed on the semiconductor substrate **51**. The plurality of structures are separated from one another by the first trenches. While not shown, after defining the first trenches, buried bit lines (BBL) may be additionally formed in the bodies **53**A using a substance such as a metal nitride. This will be described later.

[0106] Next, an interlayer dielectric layer (not shown) is formed to fill the spaces between the bodies **53**A. The interlayer dielectric layer may include an oxide layer such as a silicon oxide. The interlayer dielectric layer may be planarized through CMP (chemical mechanical polishing) or the like until the surfaces of the hard mask layer patterns **22**A are exposed. Reference may be made to the interlayer dielectric layer **25**A of FIG. **3**A for the interlayer dielectric layer.

[0107] Referring to FIG. **11**B, photoresist patterns (not shown) are formed to extend in a direction crossing with the bodies **53**A, that is, a first direction. The hard mask layer patterns **52**A and the bodies **53**A are etched using the photoresist patterns as an etch barrier. According to this fact, a plurality of pillars **54** are formed. When etching the bodies **53**A, the hard mask layer patterns **52**A may also be etched. Accordingly, the hard mask layer patterns **52**A may remain as indicated by the reference numeral **52**.

[0108] The plurality of pillars **54** are separated from one another by second trenches **55**. The bodies **53**A remain as indicated by the reference numeral **53**, and the pillars **54** are formed on the bodies **53**. The plurality of pillars **54** may have a matrix arrangement. Each pillar **54** may have four sidewalls. The sidewalls of each pillar **54** which oppose each other in any one direction (the first direction in which the pillars **54** are separated from one another by the first trenches) may contact the interlayer dielectric layer. That is to say, the interlayer dielectric layer is formed between the pillars **54** which are arranged in the first direction. The other laterally opposing sidewalls (hereinafter, referred to as 'first sidewalls and second sidewalls') of the pillars **54** which are arranged in the second direction are exposed by the second trenches **55**. The second trenches **55** extend in the direction crossing with the first trenches, and may have a depth shallower than the first trenches. Accordingly, the pillars **54** are formed in a plural number on each body **53**. The plurality of bodies **53** are

separated from one another by the first trenches, and the plurality of pillars **54** are separated from one another by the second trenches **55**.

[0109] Referring to FIG. **11**C, a gate dielectric layer **56** is formed on the first sidewalls and the second sidewalls of the pillars **54**. The gate dielectric layer **56** may be formed through oxidation such as thermal oxidation or plasma oxidation. The gate dielectric layer **56** may be formed on the entire surface through chemical vapor deposition (CVD) or atomic layer deposition (ALD). The gate dielectric layer **56** may include a silicon oxide, a high-k substance, or the like.

[0110] Next, preliminary first gate electrodes **57**A and preliminary shield gate electrodes **58**A are respectively formed on the first sidewalls and the second sidewalls of the pillars **54** which are formed with the gate dielectric layer **56**. The preliminary shield gate electrodes **58**A and the preliminary first gate electrodes **57**A may extend in the first direction. In order to form the preliminary shield gate electrodes **58**A and the preliminary first gate electrodes **57**A, an etch-back process may be performed after forming a first conductive layer on the entire surface. According to this fact, the preliminary shield gate electrodes **58**A and the preliminary first gate electrodes **57**A may be simultaneously formed. The first conductive layer may include an oxide, a metal nitride with low reactivity or a low resistance metal. For example, the preliminary shield gate electrodes **58**A may include TIN, TiAlN, WN, TaN, W, Al, Ru, Pt, Au, or the like. Hereafter, in the present embodiment, the first conductive layer may be formed using a titanium nitride (TiN).

[0111] Referring to FIG. **11**D, a first dielectric layer **59**A is formed to fill the spaces between the pillars **54** which are formed with the preliminary first gate electrodes **57**A and the preliminary shield gate electrodes **58**A. The first dielectric layer **59**A may include an oxide such as a silicon oxide. The first dielectric layer **59**A may be planarized through CMP or the like until the surfaces of the hard mask layer patterns **52** are exposed.

[0112] Referring to FIG. **11**E, photoresist patterns **60** are formed. The photoresist patterns **60** may have shapes which expose the upper surfaces of the preliminary shield gate electrodes **58**A.

[0113] The preliminary shield gate electrodes **58**A are etched by a predetermined depth using the photoresist patterns **60** as an etch barrier. According to this fact, shield gate electrodes **58** are formed, and gaps **61** are defined on the shield gate electrodes **58**.

[0114] Referring to FIG. **11**F, a second dielectric layer **62**A is formed to fill the gaps **61**. The second dielectric layer **62**A may include an oxide such as a silicon oxide. Also, the second dielectric layer **62**A may include a nitride such as a silicon nitride. The second dielectric layer **62**A may be planarized through CMP or the like until the surfaces of the hard mask layer patterns **52** are exposed. The second dielectric layer **62**A is formed on the shield gate electrodes **58**.

[0115] Referring to FIG. **11**G, the preliminary first gate electrodes **57**A, the first dielectric layer **59**A and the second dielectric layer **62**A are recessed by a predefined depth. According to this fact, first recesses **63** are defined. The depth of the first recesses **63** may be lower than the upper surfaces of the pillars **54**. First gate electrodes **57** are formed by the first recesses **63**, and the upper surfaces of the first gate electrodes **57** are exposed. First and second dielectric layers **59** and **62** remain on the bottoms of the first recesses **63**. The first recesses **63** are defined such that the shield gate electrodes **58** are not exposed. In other wards, the second dielectric layer **62** remains by a predetermined thickness on the shield gate electrodes **58**.

[0116] By forming the first gate electrodes **57** as described above, double gate structures including the shield gate electrodes **58** and the first gate electrodes **57** are formed in a self-aligned manner on the first sidewalls and the second sidewalls of the pillars **54**. The shield gate electrodes **58** and the first gate electrodes **57** have a height difference. The shield gate electrodes **58** have a height lower than the first gate electrodes **57**. While the first gate electrodes **57** serve as the gate electrodes of vertical channel transistors, the shield gate electrodes **58** do not serve as gate electrodes. The shield gate electrodes **58** may perform a function of shielding electric fields by the neighbor first gate electrodes **57**, by which it is possible to minimize a neighbor gate effect.

[0117] Referring to FIG. **11**H, spacers **64** are formed on both sidewalls of the first recesses **63**. The spacers **64** may be formed using an oxide such as a silicon oxide. For example, the spacers **64** are formed by depositing a silicon oxide on the entire surface and then performing etch-back. The thickness of the spacers **64** may be the same as the thickness of the underlying first gate electrodes **57**.

[0118] The first dielectric layer **59** is partially etched back to be self-aligned with the spacers **64**. By this fact, the upper portions of the sidewalls of the first gate electrodes **57** are exposed. When etching back the first dielectric layer **59**, a depth is controlled such that the shield gate electrodes **58** are not exposed. Namely, the second dielectric layer **62** remains on the shield gate electrodes **58**.

[0119] By etching back the first dielectric layer **59** using the spacers **64** in this way, the upper portions of the sidewalls of the first gate electrodes **57** are exposed as indicated by the reference numeral **65**.

[0120] Referring to FIG. **11**I, second gate electrodes **66** are formed to fill the spaces defined on the first dielectric layer **59**. The second gate electrodes **66** may extend in the first direction. In order to form the second gate electrodes **66**, an etch-back process may be performed after forming a second conductive layer on the entire surface. The second conductive layer may include W, Al, Ru, Pt, Au, or the like. Hereafter, the second conductive layer may be formed of tungsten (W). The second gate electrodes **66** may have buried structures.

[0121] The second gate electrodes **66** are connected with the first gate electrodes **57**, and may be isolated from the shield gate electrodes **58** by the first and second dielectric layers **59** and **62**.

[0122] As can be readily seen from the above descriptions, the vertical channel transistors in accordance with the third embodiment of the present invention has a double gate structure in which the first gate electrodes **57** and the shield gate electrodes **58** are formed on both sidewalls of the pillars **54**.

[0123] Referring to FIG. **11**J, the surfaces of the second gate electrodes **66** are recessed.

[0124] A capping layer **67** is formed to fill the spaces which are defined on the recessed second gate electrodes **66**. The capping layer **67** may include an oxide layer such as a silicon oxide. By forming the capping layer **67** in this way, the first and second gate electrodes **57** and **58** are isolated from surrounding structures.

[0125] FIGS. **12**A to **12**C are views explaining a method for fabricating a capacitor of the semiconductor device to which the vertical channel transistors in accordance with the third embodiment of the present invention are applied.

[0126] Referring to FIG. **12**A, contact holes **68** are defined by removing the hard mask layer patterns **52**. Since the spacers **64** and the capping layer **67** are a silicon oxide and the hard mask layer patterns **52** are a silicon nitride, the hard mask layer patterns **52** may be removed through a wet etching using a phosphoric acid. According to this fact, the contact holes **68** are defined in a self-defined manner by the capping layer **67** and the spacers **64**. The upper surfaces of the pillars **54** are exposed on the bottoms of the contact holes **68**.

[0127] Referring to FIG. **12**B, contact plugs **69** are formed to be buried in the contact holes **68**. The contact plugs **69** may include a polysilicon, a metal or the like. For example, after depositing a polysilicon to fill the contact holes **68**, a planarization process may be performed. The spacers **64** surround the sidewalls of the contact plugs **69**. While not shown, ion implantation for forming sources/drains may be carried out before forming the contact plugs **69**.

[0128] Referring to FIG. **12**C, storage nodes **70** of capacitors are formed on the contact plugs **69**. The storage nodes **70** may have pillar shapes. In another embodiment, the storage nodes **70** may have cylinder shapes. As a method for forming the storage nodes **70**, well-known methods may be adopted. For example, after forming a mold layer (not shown), open parts are formed by etching the mold layer, and the storage nodes **70** are formed in the open parts. Then, the mold layer is removed through a full dip-out process.

[0129] While not shown, supporters for supporting the outer walls of the storage nodes **70** may be additionally formed. For example, a substance for supporters is formed on the mold layer, and supporters may be formed by partially etching the substance for supporters before performing the full dip-out process. Furthermore, a dielectric layer and plate nodes may be additionally formed on the storage nodes **70**.

[0130] FIG. **13** is a view illustrating vertical channel transistors in accordance with a fourth embodiment of the present invention.

[0131] Referring to FIG. **13**, vertical channel transistors in accordance with a fourth embodiment of the present invention may include pillars **54**, first gate electrodes **57**, and second gate electrodes **66**.

[0132] First, a plurality of pillars **54** are formed on a semiconductor substrate **51** to vertically project from the surface of the semiconductor substrate **51**. Bodies **53** may be further formed under the pillars **54**. The pillars **54** may vertically project from the surfaces of the bodies **53**. The plurality of pillars **54** may have a matrix arrangement. The pillars **54** may be quadrangular pillars each of which has a plurality of sidewalls. The pillars **54** may be arranged to be isolated by an interlayer dielectric layer (not shown) in a first direction Y, and the first and second sidewalls of the pillars **54** laterally opposing each other may be exposed in a second direction X. Each pillar **54** may have a source region, a drain region and a channel region (not numbered). The drain region may be formed in top portion of the pillar **54**, and the source region may be formed in bottom portion of the pillar **54**. The channel region may be formed between the drain region and the source region. The semiconductor substrate **51**, the bodies **53** and the pillars **54** include a silicon-containing substance. For example, a silicon substrate or a silicon-germanium substrate may be used. Accordingly, the pillar **54** may include a semiconductor pillar, a silicon pillar or a silicon-germanium pillar.

[0133] A gate dielectric layer **56** is formed on the first sidewalls and the second sidewalls of the pillars **54**. The gate dielectric layer **56** may include a silicon oxide or a high-k substance.

[0134] The first gate electrodes **57** are formed on the gate dielectric layer **56** to cover the first sidewalls of the pillars **54**. The first gate electrodes **57** may be formed to be lower than the height of the pillars **54**. The first gate electrodes **57** may become vertical gate electrodes.

[0135] The second gate electrodes **66** which are connected to the upper portions of the sidewalls of the first gate electrodes **57** are formed between the plurality of pillars **54**. The second gate electrodes **66** may serve as word lines. The second gate electrodes **66** may have shapes which are buried in the upper portions of the spaces defined between the plurality of pillars **54**. For example, the second gate electrodes **66** may be buried between the hard mask layer patterns **52**. A first dielectric layer **59** may be formed between the first gate electrodes **57** and adjoining pillars **54**. The first gate electrodes **57** and a second dielectric layer **62** may have the same height. The first dielectric layer **59** may have a height lower than the first gate electrodes **57** and the second dielectric layer **62**. The second dielectric layer **62** may be formed on the facing-away sidewalls of the pillars **54**. The first dielectric layer **59** may be recessed by a predetermined depth, and the second gate electrodes **66** may be formed on the first dielectric layer **59** which is recessed. Spacers **64** may be formed on the second dielectric layer **62** and the first gate electrodes **57**. The second gate electrodes **66** may be isolated from the surrounding structures by the spacers **64**. A capping layer **67** may be additionally formed on the second gate electrodes **66**.

[0136] The first gate electrodes **57** have line-shaped vertical gate structures which extend in the first direction Y. The second gate electrodes **66** have shapes which extend in the first direction Y in the same manner as the first gate electrodes **57**. The first gate electrodes **57** may include a metal nitride or a low resistance metal. For example, the first gate electrodes **57** may include TIN, TiAlN, WN, TaN, W, Al, Ru, Pt, Au, or the like. The second gate electrodes **66** may include W, Al, Ru, Pt, Au, or the like.

[0137] According to FIG. **13**, the vertical channel transistors in accordance with the fourth embodiment of the present invention have single gate structures in which the first gate electrodes **57** are formed on only one sidewalls of the pillars **54**. The first gate electrodes **57** become the gate electrodes of vertical channel transistors. Furthermore, as only the first gate electrodes **57** are formed on the sidewalls of the pillars **54**, the first gate electrodes **57** may be formed to have a substantial thickness. According to this fact, gate resistance may be reduced. In particular, because only the first gate electrodes **57** are formed without forming shield gate electrodes, a neighbor gate effect may be originally prevented.

[0138] FIG. **14** is a perspective view illustrating a semiconductor device to which the vertical channel transistors in accordance with the fourth embodiment of the present invention are applied.

[0139] Referring to FIG. **14**, vertical channel transistors include first gate electrodes **404**, second gate electrodes **405**, and pillars **403**. As buried bit lines **402** and capacitors **407** are connected to the vertical channel transistors, a semiconductor device such as a DRAM may be realized. The buried bit lines **402** may be electrically connected with the bottom portions of the pillars **403**. The buried bit lines **402** may be vertically formed on a semiconductor substrate **401** and may extend in

a first direction. The first gate electrodes **404** and the second gate electrodes **405** may extend in a second direction perpendicularly crossing with the first direction. The capacitors **407** may be electrically connected with the top portions of the pillars **403**. Contact plugs **406** may be additionally formed between the capacitors **407** and the pillars **403**. While not shown, the capacitors **407** may include storage nodes, a dielectric layer and plate nodes. The vertical channel transistors may be applied not only to a memory such as a DRAM but also to a nonvolatile memory such as a flash memory.

[0140] FIGS. **15**A to **15**F are views explaining an exemplary method for fabricating the vertical channel transistors in accordance with the fourth embodiment of the present invention. Unlike the third embodiment, when defining gaps, shield gate electrodes are entirely removed. Hereinbelow, reference will be made to FIGS. **11**A to **11**D for processes before defining the gaps.

[0141] Referring to FIG. **15**A, photoresist patterns **60** are formed. The photoresist patterns **60** may have shapes which expose the upper surfaces of the preliminary shield gate electrodes **58**A.

[0142] The preliminary shield gate electrodes **58**A are entirely etched using the photoresist patterns **60** as an etch barrier. According to this fact, gaps **61** are defined. The preliminary shield gate electrodes **58**A removed in this way may become sacrificial gate electrodes.

[0143] By entirely removing the preliminary shield gate electrodes **58**A, only preliminary first gate electrodes **57**A remain on the one sidewalls of the pillars **54**.

[0144] Referring to FIG. **15**B, a second dielectric layer **62**A is formed to fill the gaps **61**. The second dielectric layer **62**A may include an oxide such as a silicon oxide. Also, the second dielectric layer **62**A may include a nitride such as a silicon nitride. The second dielectric layer **62**A may be planarized through CMP or the like until the surfaces of the hard mask layer patterns **52** are exposed.

[0145] Referring to FIG. **15**C, the preliminary first gate electrodes **57**A, the first dielectric layer **59**A and the second dielectric layer **62**A are recessed by a predefined depth. According to this fact, first recesses **63** are defined. The depth of the first recesses **63** may be lower than the surfaces of the pillars **54**. First gate electrodes **57** are formed by the first recesses **63**, and the upper surfaces of the first gate electrodes **57** are exposed. The first and second dielectric layers **59** and **62** remain on the bottoms of the first recesses **63**.

[0146] The first gate electrodes **57** serve as the gate electrodes of the vertical channel transistors. By not forming shield gate electrodes, a neighbor gate effect by neighbor gates may be originally prevented.

[0147] Referring to FIG. **15**D, spacers **64** are formed on both sidewalls of the first recesses **63**. The spacers **64** may be formed of an oxide such as a silicon oxide. For example, the spacers **64** may be formed by depositing a silicon oxide on the entire surface and etching back the silicon oxide. The thickness of the spacers **64** may be the same as the thickness of the underlying first gate electrodes **57**.

[0148] The first dielectric layer **59** is partially etched back to be self-aligned with the spacers **64**. Due to this fact, the upper portions of the sidewalls of the first gate electrodes **57** are exposed.

[0149] By etching back the first dielectric layer **59** using the spacers **64** in this way, the upper portions of the sidewalls of the first gate electrodes **57** are exposed as indicated by the reference numeral **65**.

[0150] Referring to FIG. **15**E, second gate electrodes **66** are formed to fill the spaces defined on the first dielectric layer **59**. The second gate electrodes **66** may extend in the first direction. In order to form the second gate electrodes **66**, an etch-back process may be performed after forming a second conductive layer on the entire surface. The second conductive layer may include W, Al, Ru, Pt, Au, or the like. The second conductive layer may be formed of tungsten (W). The second gate electrodes **66** may have buried structures.

[0151] The second gate electrodes **66** are connected with the upper portions of the sidewalls of the first gate electrodes **57**.

[0152] As can be readily seen from the above descriptions, the vertical channel transistors in accordance with the fourth embodiment of the present invention have single gate structures in which the first gate electrodes **57** are formed on only any one sidewalls of the pillars **54**.

[0153] Referring to FIG. **15**F, the surfaces of the second gate electrodes **66** are recessed.

[0154] A capping layer **67** is formed to fill the spaces defined on the second gate electrodes **66** which are recessed. The capping layer **67** may include an oxide such as a silicon oxide.

[0155] Contact plugs and capacitors are subsequently formed. Reference may be made to FIGS. **12**A to **12**C for a method for forming the contact plugs and the capacitors.

[0156] A method for forming the buried bit lines in accordance with the first to fourth embodiments of the present invention will be described below. Hereinbelow, explanations will be made for a method for forming the buried bit lines of the semiconductor device to which the vertical channel transistors in accordance with the first embodiment shown in FIG. **2** is applied. The same method may be applied to the other embodiments. The buried bit lines may be formed before forming the first dielectric layer in FIG. **3**B. That is to say, after forming the bodies shown in FIG. **3**A, the buried bit lines may be formed before forming the first dielectric layer in FIG. **3**B.

[0157] FIGS. **16**A to **16**K are views explaining a method for forming a buried bit line of the semiconductor device to which the vertical channel transistors in accordance with the embodiments of the present invention are applied.

[0158] Referring to FIG. **16**A, passivation layers are formed on the entire surface including bodies (see the reference numeral **24**A of FIG. **4**A). As the passivation layers, a first passivation layer **71** and a second passivation layer **72** may be stacked. Each of the first passivation layer **71** and the second passivation layer **72** may include an oxide, a nitride, or the like. Because the first passivation layer **71** and the second passivation layer **72** should have etching selectivities, different substances are selected as the first passivation layer **71** and the second passivation layer **72**. For example, if an oxide is used to form the first passivation layer **71**, a substance with an etching selectivity with respect to the oxide is selected to form the second passivation layer **72**. If the first passivation layer **71** is formed of an oxide, the second passivation layer **72** may be formed of a nitride.

[0159] A first sacrificial layer **73** is formed on the entire surface of a resultant structure including the second passivation layer **72** in such a way as to gapfill first trenches **23** between the bodies **24**A. A substance having a different etching selectivity with respect to the first and second passivation layers **71** and **72** may be used to form the first sacrificial layer **73**. The first sacrificial layer **73** may include an oxide layer, a

nitride layer, a silicon layer, or the like. Here, while a substance used as the first and second passivation layers **71** and **72** may be repeatedly used as the first sacrificial layer **73**, a different substance is used to have a different etching selectivity. Hereinbelow, as the first sacrificial layer **73**, a silicon layer may be used.

[0160] Referring to FIG. **16**B, the first sacrificial layer **73** is planarized. The planarization of the first sacrificial layer **73** includes a CMP (chemical mechanical polishing) process. Successively, an etch-back process is performed. By the etch-back process, first sacrificial layer patterns **73**A which are recessed are formed. During the etch-back process, the second passivation layer **72** is not etched since it has an etching selectivity different from that of the first sacrificial layer **73**.

[0161] Referring to FIG. **16**C, portions of the second passivation layer **72** which are exposed by the recessed first sacrificial layer patterns **73**A are selectively removed. By this fact, second passivation layer patterns **72**A with the same height as the first sacrificial layer patterns **73**A are formed. In order to remove the second passivation layer **72**, wet etching or dry etching may be adopted.

[0162] Referring to FIG. **16**D, a second sacrificial layer **74** is formed on the entire surface of the resultant structure formed with the second passivation layer patterns **72**A. The second sacrificial layer **74** gapfills the first trenches **23**. The second sacrificial layer **74** may be formed of a substance with a different etching selectivity from the first passivation layer **71**. The second sacrificial layer **74** may include an oxide layer, a nitride layer, a silicon layer, or the like. Here, while a substance used as the first passivation layer **71** may be repeatedly used as the second sacrificial layer **74**, a different substance is used to have a different etching selectivity. Hereinbelow, according to the present embodiment, as the second sacrificial layer **74**, a silicon layer may be used.

[0163] The second sacrificial layer **74** is planarized. The planarization of the second sacrificial layer **74** includes a CMP (chemical mechanical polishing) process. Successively, an etch-back process is performed. By the etch-back process, second sacrificial layer patterns **74**A which are recessed are formed. During the etch-back process, the first passivation layer **71** is not etched since it has an etching selectivity different from that of the second sacrificial layer **74**.

[0164] Referring to FIG. **16**E, a third passivation layer **75** is formed on the entire surface of the resultant structure including the second sacrificial layer patterns **74**A. The third passivation layer **75** may include an oxide layer, a nitride layer, a silicon layer, or the like. The third passivation layer **75** may be formed of a substance with a different etching selectivity from the first passivation layer **71**. Therefore, different substances are selected as the first passivation layer **71** and the third passivation layer **75**. For example, if an oxide layer is used as the first passivation layer **71**, a substance with a different etching selectivity from the oxide layer is selected as the third passivation layer **75**. If the oxide layer is used as the first passivation layer **71**, a nitride layer may be used as the third passivation layer **75**.

[0165] Referring to FIG. **16**F, the third passivation layer **75** is selectively etched through spacer etching. According to this fact, third passivation layer patterns **75**A are formed. The third passivation layer patterns **75**A have the forms of spacers which cover the sidewalls of the bodies **24**A and the hard mask layer patterns **22**A. The third passivation layer patterns **75**A have a height that covers the sidewalls of the bodies **24**A and the hard mask layer patterns **22**A on the second sacrificial layer patterns **74**A. The third passivation layer patterns **75**A cover the first passivation layer **71**. By the third passivation layer patterns **75**A, the underlying second sacrificial layer patterns **74**A are exposed.

[0166] The second sacrificial layer patterns **74**A are removed. The second sacrificial layer patterns **74**A are removed using dry etching or wet etching.

[0167] As the second sacrificial layer patterns **74**A are removed in this way, preliminary open parts **76**A and **76**B are formed between the third passivation layer patterns **75**A and the second passivation layer patterns **72**A. The preliminary open parts **76**A and **76**B expose portions of the first passivation layer **71**. The preliminary open parts **76**A and **76**B are open with the forms of lines which extend along the sidewalls of the bodies **24**A. In particular, the preliminary open parts **76**A and **76**B are open on both sidewalls of the bodies **24**A.

[0168] Referring to FIG. **16**G, the portions of the first passivation layer **71** which are exposed through the preliminary open parts **76**A and **76**B are selectively removed. By this fact, open parts **77**A and **77**B are formed. The sidewalls of the bodies **24**A, which are formed with the open parts **77**A and **77**B, are covered by first passivation layer patterns **71**A, the second passivation layer patterns **72**A and the third passivation layer patterns **75**A. When viewed from the positions of the open parts **77**A and **77**B, the lower sidewalls of the bodies **24**A are covered by the first passivation layer patterns **71**A and the second passivation layer patterns **72**A, and the upper sidewalls of the bodies **24**A are covered by the first passivation layer patterns **71**A and the third passivation layer patterns **75**A. When forming the open parts **77**A and **77**B, portions of the first passivation layer **71** which are formed on the hard mask layer patterns **22**A may be simultaneously removed.

[0169] The open parts **77**A and **77**B may be open with the forms of lines which extend along the sidewalls of the bodies **24**A. Specifically, the open parts **77**A and **77**B are simultaneously formed on both sidewalls of the bodies **24**A. Thus, a series of processes for forming the open parts **77**A and **77**B are referred to as a double-side-contact (DSC) process. The double-side-contact (DSC) process is contrasted with an OSC (one-side-contact) process. While the OSC process is a process for opening only any one of both sidewalls of each body, the double-side-contact (DSC) process is a process for opening both sidewalls of each body **24**A.

[0170] The double-side-contact (DSC) process as described above is simple unlike the OSC process. Also, tilt ion implantation and an OSC mask may not be used. In particular, the height of the open parts **77**A and **77**B may be uniformized.

[0171] Referring to FIG. **16**H, plasma doping **78** is performed. At this time, portions of the sidewalls of the bodies **24**A which are exposed through the open parts **77**A and **77**B are doped. Accordingly, source/drain regions **79** are formed. The source/drain regions **79** become source regions or drain regions of vertical channel transistors.

[0172] The source/drain regions **79** may be formed by performing tilt ion implantation instead of the plasma doping **78**. As another method for forming the source/drain regions **79**, doped polysilicon in situ doped with a dopant may be used. For example, by performing annealing after gapfilling the doped polysilicon, the dopant in the doped polysilicon may be diffused into the bodies **24**A.

[0173] Referring to FIG. **16**I, a conductive layer **80** is formed on the entire surface of the resultant structure including the open parts **77**A and **77**B. The conductive layer **80**

includes a metal such as a near-noble metal and a refractory metal. The conductive layer **80** includes a metal capable of silicidation. For example, the conductive layer **80** includes any one selected among cobalt (Co), titanium (Ti), tantalum (Ta), nickel (Ni), tungsten (W), platinum (Pt) and palladium (Pd). The conductive layer **80** is formed using chemical vapor deposition (CVD) or atomic layer deposition (ALD). The deposition thickness of the conductive layer **80** is determined to a thickness capable of filling at least the open parts **77**A and **77**B. Such a thickness is selected to permit full silicidation in a subsequent silicidation process.

[0174] Referring to FIG. **16**J, annealing **81** is performed. According to this fact, silicidation is effected in which the conductive layer **80** and the bodies **24**A react with each other. Since the conductive layer **80** is a metal and the material of the bodies **24**A contains silicon, a metal silicide **82** is formed by the reaction of the conductive layer **80** and the bodies **24**A. The metal silicide **82** includes any one selected among a cobalt silicide, a titanium silicide, a tantalum silicide, a nickel silicide, a tungsten silicide, a platinum silicide and a palladium silicide. The annealing **81** includes rapid thermal annealing (RTA). The rapid thermal annealing (RTA) may be performed at different temperatures depending upon the kinds of the bodies **24**A and the conductive layer **80**. For example, in the case where the conductive layer **80** is formed using cobalt (Co), an annealing temperature range may be approximately 400° C. to approximately 800° C. The metal silicide **82** may be formed to have a fully silicidated (FUSI) structure. By sufficiently performing silicidation from both sidewalls of the bodies **24**A, the portions of the bodies **24**A which are exposed through the open parts **77**A and **77**B are fully silicidated. Through full silicidation, the metal silicide **82** is formed in the bodies **24**A.

[0175] After forming the metal silicide **82**, an unreacted conductive layer **80**A remains. The metal silicide **82**, which is formed through the silicidation process as described above, becomes buried bit lines (BBL). Hereinbelow, the metal silicide is referred to as buried bit lines **82**.

[0176] Referring to FIG. **16**K, the unreacted conductive layer **80**A is removed. The unreacted conductive layer **80**A may be removed through wet etching.

[0177] Meanwhile, in the case where the conductive layer **80** is formed using cobalt, in order to form a cobalt silicide, rapid thermal annealing (RTA) is performed at least twice. For example, primary annealing and secondary annealing are performed. The primary annealing is performed at a temperature of approximately 400° C. to approximately 600° C., and the secondary annealing is performed at a temperature of approximately 600° C. to approximately 800° C. By the primary annealing, a cobalt silicide with the phase of $CoSi_x$ (x=approximately 0.1 to approximately 1.5) is formed. By the secondary annealing, a cobalt silicide with the phase of $CoSi_2$ is obtained. Among cobalt silicides, the cobalt silicide with the phase of $CoSi_2$ has smallest specific resistance. Unreacted cobalt is removed between the primary annealing and the secondary annealing. The unreacted cobalt may be removed using a mixed chemical of sulphuric acid (H_2SO_4) and hydrogen peroxide (H_2O_2).

[0178] The vertical channel transistors in accordance with the embodiments of the present invention may be included in an electronic apparatus. The electronic apparatus may be a PDA, a laptop computer, a notebook computer, a web tablet, a wireless phone, a mobile phone, a digital music player, a wired or wireless electronic appliance, or one of composite electronic apparatuses including at least two of them. The electronic apparatus may include memories, and the memories may include the vertical channel transistors in accordance with the embodiments of the present invention.

[0179] The semiconductor devices in accordance with the embodiments of the present invention may be used to realize a memory system. The memory system may include memories for storing a large amount of data and a memory controller. The memory controller controls the memories to read or write data from or to the memories in response to a read/write request from a host. The memory controller may constitute an address mapping table for mapping the addresses provided from the host, for example, a mobile terminal or a computer system, into physical addresses. The memories may include the vertical channel transistors in accordance with the embodiments of the present invention.

[0180] As is apparent from the above descriptions, according to the embodiments of the present invention, it is possible to form self-aligned vertical gate electrodes with a single gate structure or a double gate structure.

[0181] In the embodiments of the present invention, as the single gate structure is formed through forming only one vertical gate electrode on the sidewall of a pillar, the vertical gate electrode may be formed thick. According to this fact, gate resistance may be reduced. Also, as the single gate structure is formed through forming one vertical gate electrode without a shield gate electrode, a neighbor gate effect may be minimized.

[0182] Furthermore, in the embodiments of the present invention, even when a double gate structure is formed through respectively forming a shield gate electrode and a vertical gate electrode on both sidewalls of a pillar, the vertical gate electrode may be formed thick by decreasing the height of the shield gate electrode. Accordingly, gate resistance may be reduced. Moreover, a neighbor gate effect may be minimized due to the presence of the shield gate electrode.

[0183] While the present invention has been described with respect to the specific embodiments, it will be apparent to those skilled in the art that various changes and modifications may be made without departing from the spirit and scope of the invention as defined in the following claims.

1. A method for fabricating vertical channel transistors, comprising:

forming a plurality of pillars which have laterally opposing both sidewalls, over a substrate;

forming a gate dielectric layer on both sidewalls of the pillars;

forming first gate electrodes which cover any one sidewalls of the pillars and shield gate electrodes which cover the other sidewalls of the pillars and have a height lower than the first gate electrodes, over the gate dielectric layer; and

forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes.

2. The method according to claim **1**, wherein the forming of the first gate electrodes and the shield gate electrodes comprises:

forming the first gate electrodes and preliminary shield gate electrodes which respectively cover both sidewalls of the pillars;

filling a gap between each of the plurality of pillars with a first dielectric layer;

forming the shield gate electrodes by partially removing the preliminary shield gate electrodes by a predetermined depth; and
filling a gap formed over each of the shield gate electrodes with a second dielectric layer over.

3. The method according to claim **2**, wherein the forming of the shield gate electrodes comprises:
forming photoresist patterns which expose upper surfaces of the preliminary shield gate electrodes and cover the first gate electrodes and the pillars; and
forming gaps formed over the shield gate electrodes by etching upper portions of the preliminary shield gate electrodes.

4. The method according to claim **2**, wherein the forming of the second gate electrodes comprises:
forming recesses by partially removing the first dielectric layer and the second dielectric layer; and
filling the recesses with a conductive layer to form the second gate electrodes.

5. The method according to claim **1**, further comprising:
recessing upper portions of the first gate electrodes and the second gate electrodes after the forming of the second gate electrodes; and
forming a capping layer to fill the recessed upper portions.

6. The method according to claim **1**, wherein the forming of the first gate electrodes and the shield gate electrodes comprises:
forming preliminary first gate electrodes and preliminary shield gate electrodes which respectively cover both sidewalls of the pillars;
filling a gap between each of the plurality of pillars with a first dielectric layer;
forming the shield gate electrodes by partially removing the preliminary shield gate electrodes by a predetermined depth;
filling a gap formed over each of the shield gate electrodes with a second dielectric layer; and
recessing the preliminary first gate electrodes, the first dielectric layer and the second dielectric layer by a predetermined depth to form the first gate electrodes and first recesses over the first gate electrodes.

7. The method according to claim **6**, wherein the forming of the shield gate electrodes comprises:
forming photoresist patterns which expose upper surfaces of the preliminary shield gate electrodes and cover the first gate electrodes and the pillars; and
forming gaps formed over the shield gate electrodes by etching upper portions of the preliminary shield gate electrodes.

8. The method according to claim **6**, wherein the forming of the second gate electrodes comprises:
forming spacers on both sidewalls of the first recesses;
forming second recesses by recessing the first dielectric layer to be self-aligned with the spacers; and
filling a conductive layer in the second recesses to form the second gate electrodes.

9. The method according to claim **1**, wherein the first gate electrodes have a line-shaped vertical gate structure which extends in a first direction, and the second gate electrodes have a shape which extends in the same direction as the first gate electrodes.

10. The method according to claim **1**, wherein the first gate electrodes comprise a titanium nitride layer, and the second gate electrodes comprise a tungsten layer.

11. A method for fabricating vertical channel transistors, comprising:
forming a plurality of pillars which have laterally opposing both sidewalls, over a substrate;
forming a gate dielectric layer on both sidewalls of the pillars;
forming first gate electrodes which cover any one sidewalls of both sidewalls of the pillars; and
forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes.

12. The method according to claim **11**, wherein the forming of the first gate electrodes comprises:
forming sacrificial gate electrodes and the first gate electrodes which respectively cover both sidewalls of the pillars;
filling a gap between each of the plurality of pillars with a first dielectric layer;
forming gaps by removing the sacrificial gate electrodes; and
forming a second dielectric layer to fill the gaps.

13. The method according to claim **12**, wherein the forming of the gaps comprises:
forming photoresist patterns which expose upper surfaces of the sacrificial gate electrodes and cover the first gate electrodes and the pillars; and
etching the sacrificial gate electrodes.

14. The method according to claim **12**, wherein the forming of the second gate electrodes comprises:
forming recesses by partially removing the first dielectric layer and the second dielectric layer; and
filling the recesses with a conductive layer to form the second gate electrodes.

15. The method according to claim **11**, further comprising:
recessing portions of the second gate electrodes after the forming of the second gate electrodes; and
forming a capping layer to fill the recessed portions.

16. The method according to claim **11**, wherein the forming of the first gate electrodes comprises:
forming preliminary first gate electrodes and sacrificial gate electrodes which respectively cover both sidewalls of the pillars;
filling a gap between each of the plurality of pillars with a first dielectric layer;
forming gaps by removing the sacrificial gate electrodes;
forming a second dielectric layer to fill the gaps; and
recessing the preliminary first gate electrodes, the first dielectric layer and the second dielectric layer by a predetermined depth to form the first gate electrodes and first recesses over the first gate electrodes.

17. The method according to claim **16**, wherein the forming of the gaps comprises:
forming photoresist patterns which expose upper surfaces of the sacrificial gate electrodes and cover the first gate electrodes and the pillars; and
etching the sacrificial gate electrodes.

18. The method according to claim **16**, wherein the forming of the second gate electrodes comprises:
forming spacers on both sidewalls of the first recesses;
forming second recesses by recessing the first dielectric layer to be self-aligned with the spacers; and
filling the second recesses with a conductive layer to form the second gate electrodes.

19. The method according to claim **11**, further comprising:

recessing portions of the second gate electrodes after the forming of the second gate electrodes; and

forming a capping layer to fill the recessed portions.

20. The method according to claim **11**, wherein the first gate electrodes have a line-shaped vertical gate structure which extends in a first direction, and the second gate electrodes have a shape which extends in the same direction as the first gate electrodes.

21. The method according to claim **11**, wherein the first gate electrodes comprises a titanium nitride layer, and the second gate electrodes comprises a tungsten layer.

22. A method for fabricating a semiconductor device, comprising:

forming hard mask layer patterns over a semiconductor substrate;

forming bodies by etching the semiconductor substrate using the hard mask layer patterns as an etch barrier;

forming buried bit lines in the bodies;

etching the hard mask layer patterns and upper portions of the bodies to form pillars which have laterally opposing both sidewalls;

forming first gate electrodes on any one sidewalls of both sidewalls of the pillars;

forming second gate electrodes which are connected with upper portions of sidewalls of the first gate electrodes; and

forming storage nodes which are connected with the pillars.

23. The method according to claim **22**, further comprising:

forming shield gate electrodes which have a height lower than the first gate electrodes, on the other sidewalls of the pillars.

24. The method according to claim **22**, further comprising:

recessing upper portions of the first gate electrodes and the second gate electrodes by a predetermined depth after the forming of the second gate electrodes; and

filling the recessed upper portions with a capping layer.

25. The method according to claim **22**, wherein the forming of the first gate electrodes comprises:

forming preliminary first gate electrodes and sacrificial gate electrodes which respectively cover both sidewalls of the pillars;

filling a gap between each of the plurality of pillars with a first dielectric layer;

forming gaps by removing the sacrificial gate electrodes;

forming a second dielectric layer to fill the gaps; and

recessing the preliminary first gate electrodes, the first dielectric layer and the second dielectric layer by a predetermined depth to form the first gate electrodes and first recesses over the first gate electrodes.

26. The method according to claim **25**, wherein the forming of the second gate electrodes comprises:

forming spacers on both sidewalls of the first recesses;

forming second recesses by recessing the first dielectric layer to be self-aligned with the spacers; and

filling the second recesses with a conductive layer to form the second gate electrodes.

27. The method according to claim **26**, further comprising:

forming contact holes by removing the hard mask layer patterns before the forming of the storage nodes; and

filling storage node contact plugs in the contact holes.

28. The method according to claim **22**, further comprising:

forming contact holes by removing the hard mask layer patterns before the forming of the storage nodes;

forming spacers on sidewalls of the contact holes; and

filling storage node contact plugs in the contact holes.

29-36. (canceled)

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